

N32G003x5

Data Sheet

N32G003 series adopts a 32-bit ARM Cortex®-M0 core, with a maximum operating frequency of 48MHz. It integrates up to 29.5KB embedded Flash, 3KB SRAM, 1 built-in 12bit 1Msps ADC, 1 high-speed comparator, multiple communication bus interfaces UART, I2C, SPI.

Key Features

- CPU core
 - A 32-bit ARM Cortex®-M0 core, supports single-cycle hardware multiply instruction
 - Maximum frequency of 48MHz
- Memories
 - Up to 29.5KByte embedded Flash memory, 100,000 erase/write cycles and 10-year data retention
 - Up to 3KB SRAM
- Low power management
 - RUN mode: All peripherals are configurable
 - STOP mode: TIM6, IWDG can be configured, SRAM data retained, and all IO retained
 - Power Down mode (PD mode): All power supply off, support NRST, PA1_WKUP0, PA2_WKUP1 wakeup
- Clock
 - HSI: High-speed internal RC 48MHz/40MHz(optional)
 - LSI: Low-speed internal RC 32KHz
 - MCO: Supports 1-channel clock output, which can be configured as HSI or LSI output
- Reset
 - Supports power-on/power-down/external pin reset
 - Supports programmable low voltage detection and reset
 - Supports watchdog reset, software reset
- Communication interfaces
 - 2x UART, which support asynchronous mode, multiprocessor communication mode, single-wire half-duplex mode
 - 1x SPI interface with speed up to 12MHz
 - 1x I²C interface (Master/Slave) with speed up to 1MHz
- Analog interfaces
 - 1x 12bit 1Msps high-speed ADC, up to 9 external single-ended input channels and 1 internal channel connected to the 1.2V

reference

- 1x high-speed analog comparator, whose positive terminal input supports four adjustable dropout voltages of 0mV/100mV/200mV/ 300mV
- GPIO
 - Up to 18 GPIOs that support multiplexed functions
- Beeper
 - Supports complementary output
- Timers
 - 1x 16-bit advanced timer
 1. Supports input capture, output compare
 2. Each timer has 4 independent channels, 3 of which support 6-channel complementary PWM output.
 - 1x 16-bit general purpose timer
 1. Each timer has 2 independent channels
 2. Supports input capture, output comparison, PWM output
 - 1x 16-bit basic timer, supports STOP wakeup low-power mode
 - 1x 24-bit SysTick Timer
 - 1x 12-bit Independent watchdog (IWDG)
- Programming methods
 - Supports SWD online debugging interface
- Security features
 - CRC16 calculation
 - Support multiple levels (L0/L1/L2) of read protection(RDP)
- 96-bit UID and 128-bit UCID
- Operating conditions
 - Operating voltage range: 2V~5.5V
 - Operating temperature range: -40°C ~ 105°C
 - ESD: ±4KV (HBM model), ±1KV (CDM model)
- Packages
 - QFN20(3mm x 3mm)

— TSSOP20(6.5mm x 4.4mm)

● Ordering information

Reference	Part Number
N32G003x5	N32G003F5S7, N32G003F5Q7
N32G003x4	N32G003F4S7, N32G003F4Q7

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1 Introduction

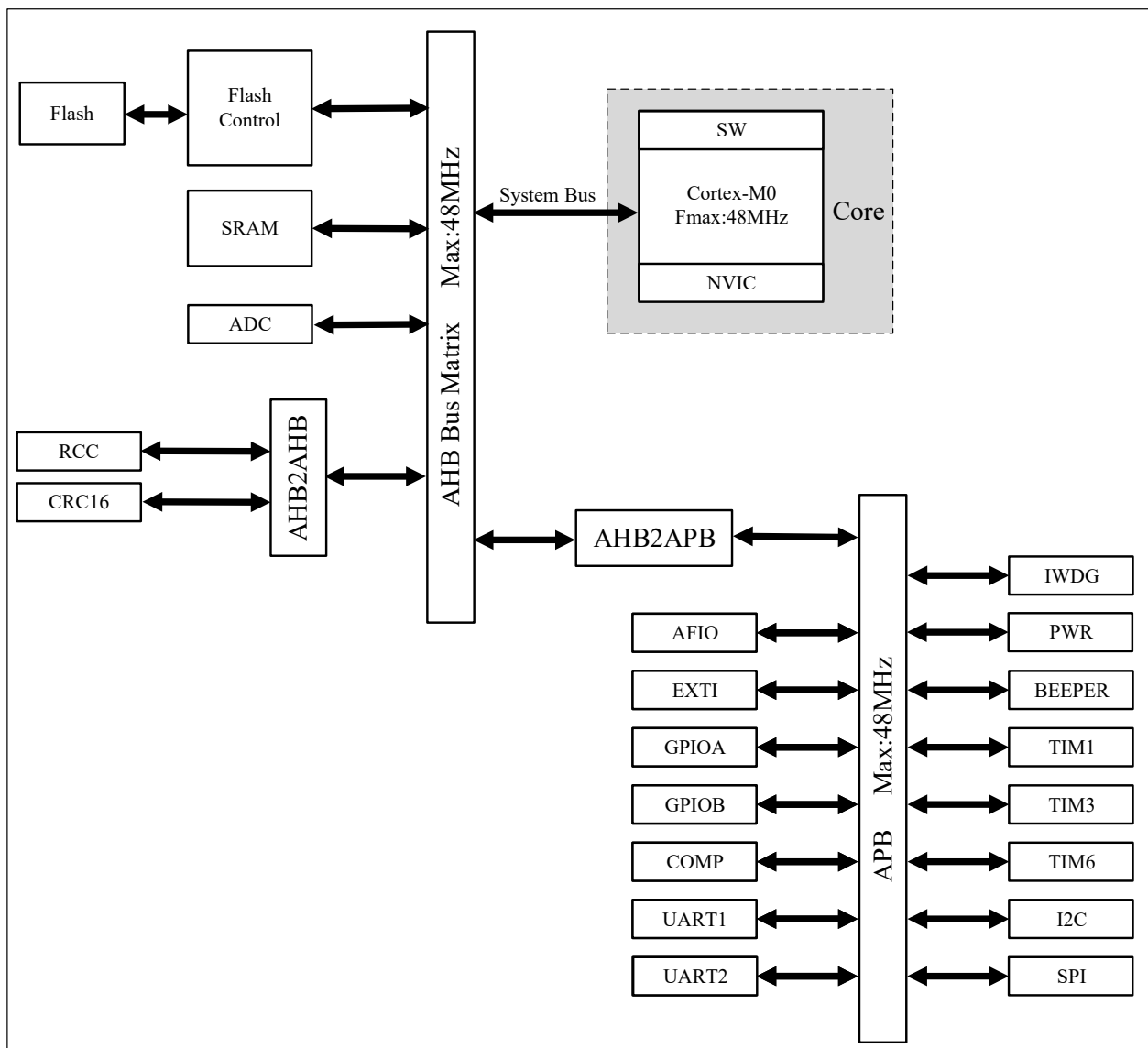
The N32G003 microcontroller series features a 32-bit ARM Cortex®-M0 core, with maximum operating frequency of 48MHz. It integrates up to 29.5KB memory Flash, and up to 3KB SRAM. The device is equipped with high-speed AHB bus, along with a low-speed peripheral bus APB and bus matrix. It offers up to 18 general-purpose I/Os, and features a diverse range of high-performance analog interfaces, including a 12-bit 1Msps ADC with up to 9 external input channels, as well as 1 high-speed comparator. The device provides a variety of digital communication interfaces, including 2xUART, 1xI²C, 1xSPI.

The N32G003 series operate reliably in the temperature range of -40°C to +105°C, and supply voltage from 2V to 5.5V. It offers multiple power modes to cater to low-power applications. Available in different packages with 20 pins.

N32G003 series microcontrollers are suitable for a variety of application scenarios such as low-power electronic cigarettes, security, smart home, motor control, power management system.

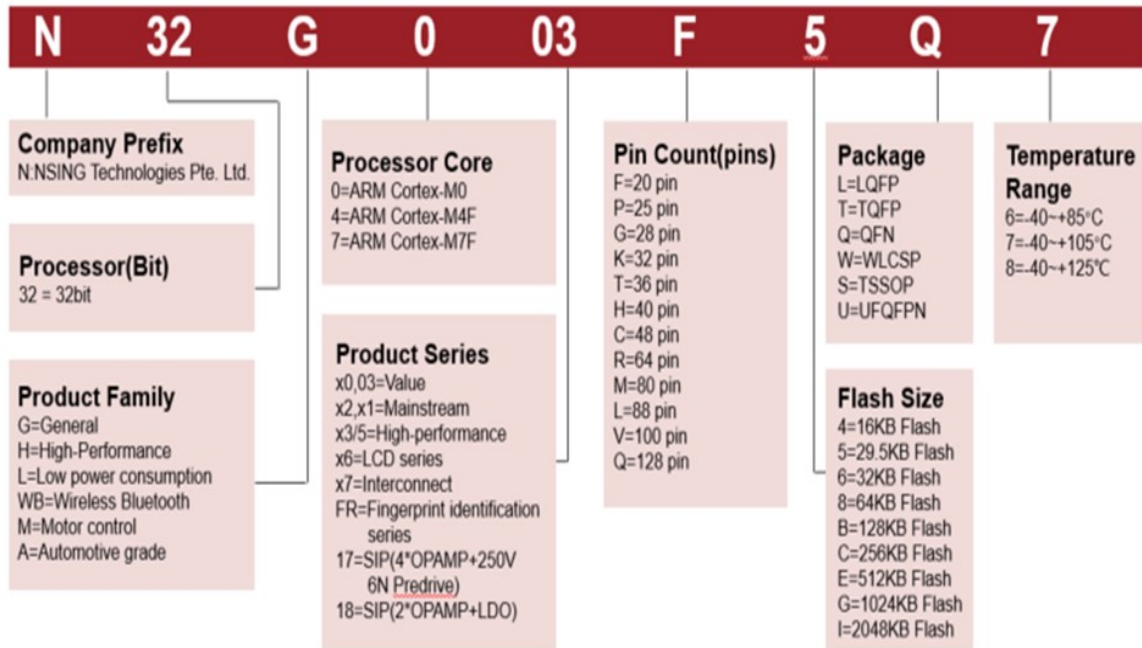
[Figure 1-1](#) shows the bus block diagram of this series of products.

Figure 1-1 N32G003 Block Diagram



1.1 Naming Convention

Figure 1-2 N32G003 Series Part Number Information



1.2 Product Configuration

Table 1-1 N32G003 Series Resource Configuration

Device		N32G003F5Q7/F4Q7	N32G003F5S7/F4S7
Flash capacity (KB)		29.5/16	29.5/16
SRAM capacity (KB)		3	3
CPU frequency		ARM Cortex [®] -M0 @48MHz	
Operating conditions		2~5.5V/-40~105°C	
Timers	General	1	1
	Advanced	1	1
	Basic	1	1
Communication interfaces	SPI	1	1
	I2C	1	1
	UART	2	2
GPIO		18	
12bit ADC		1	1
ADC channels		9 Channel	9 Channel
COMP		1	1
Beeper		1	1
Algorithm support		CRC16	CRC16
Security protection		Read protection (RDP)	
Packages		QFN20	TSSOP20

2 Functional Overview

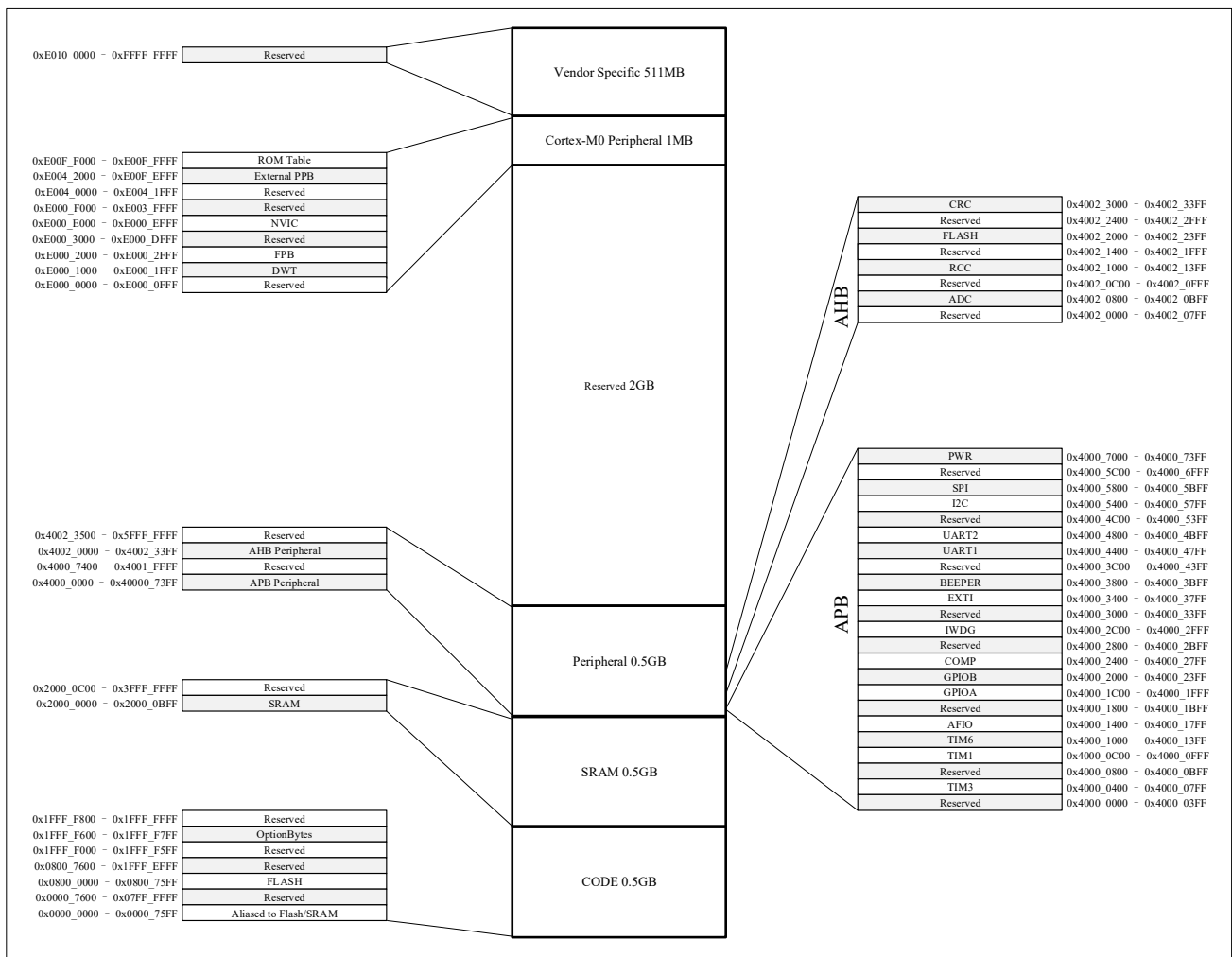
2.1 Processor Core

The N32G003 series integrates the latest generation of embedded ARM Cortex[®]-M0 processor.

2.2 Memories

N32G003 series include embedded Flash memory and embedded SRAM, following figure shows the memory address mapping.

Figure 2-1 Memory Map



2.2.1 Embedded FLASH Memory

The N32G003 integrates 29.5K bytes of embedded Flash for storing programs and data, with a page size of 512byte, supporting page erasing, word writing, word reading, half-word reading, and byte reading operations.

2.2.2 Embedded SRAM

The chip is integrated up to 3K bytes of embedded SRAM to retain data in STOP low-power mode.

2.2.3 Nested Vectored Interrupt Controller (NVIC)

The Nested Vector Interrupt Controller (NVIC) is closely linked to the processor core to enable low-latency interrupt processing and efficient processing of late interrupts. The nested vector interrupt controller manages interrupts including core exceptions.

- 16 maskable interrupt channels (not including 16 Cortex®-M0 neutral line)
- 4 programmable priorities (using 2 bit interrupt priorities)
- Low latency exception and interrupt handling
- Power management control
- Realization of system control register.

2.3 Extended Interrupt/Event Controller (EXTI)

The extended interrupt/event controller contains 20 edge detectors used for generating interrupt/event requests. Each input line can be independently configured as an event or interrupt, as well as three trigger types of rising edge, falling edge or bilateral edge, and can be masked independently. The pending register holds interrupt requests for status lines, and can be cleared by writing '1' to the corresponding bit.

2.4 Clock System

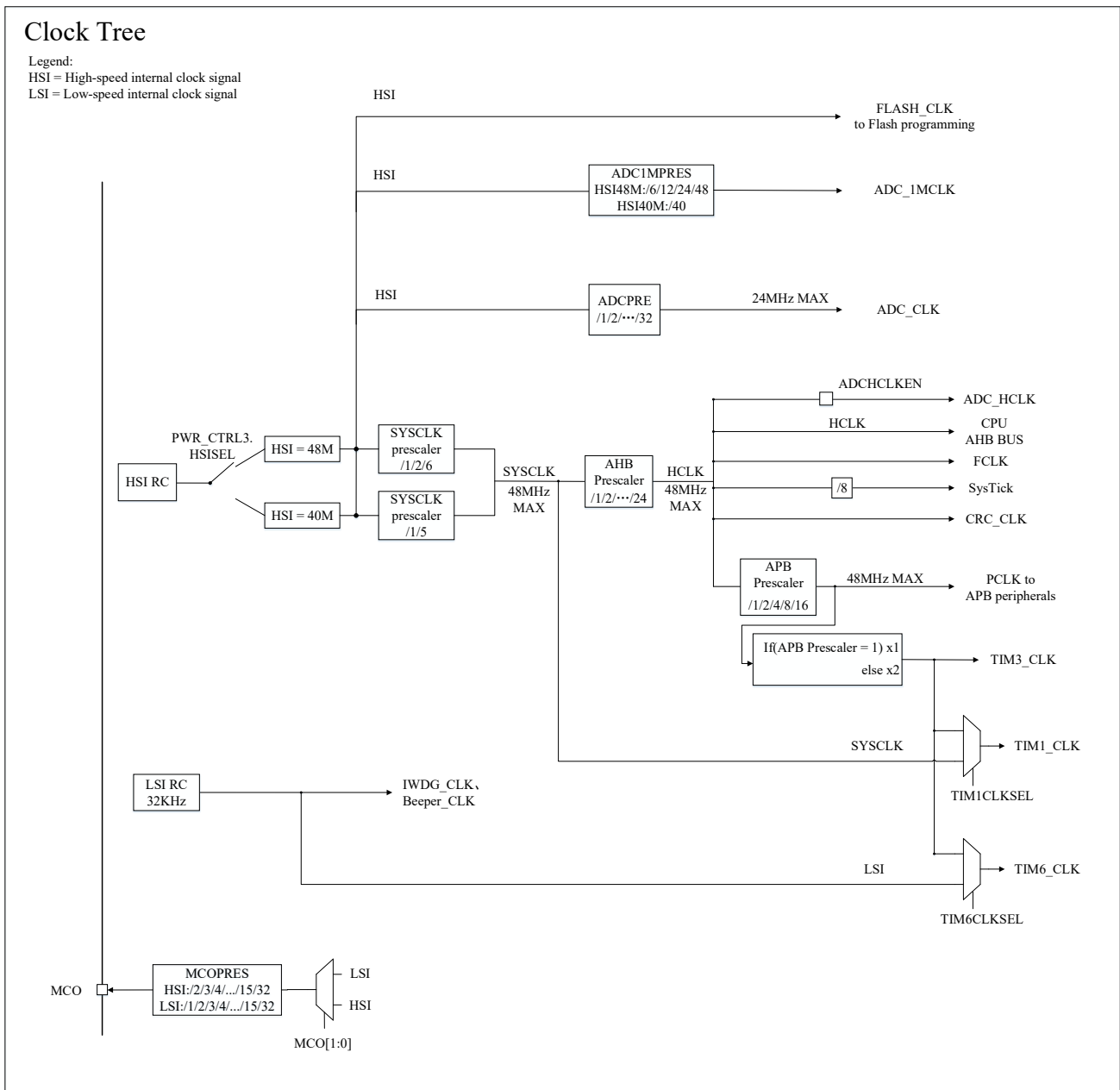
The device offers various clock options for user selection, including a high-speed internal RC oscillator HSI (48MHz or 40MHz) and a low-speed internal clock LSI (32kHz).

The HSI oscillator clock source is used to drive the system clock (SYSCLK).

The 32kHz low-speed internal RC is used as the secondary clock source, which can be selected to drive the independent watchdog (IWDG), TIM6 (for wakeup STOP mode).

Multiple prescalers can be used to configure the frequency of AHB and APB. The maximum frequency of AHB and APB is 48MHz.

Figure 2-2 Clock Tree



2.5 Boot Modes

Boot from the Flash Memory 0x08000000.

2.6 Power Supply Schemes

- V_{DD} domain: The voltage input range is 2V~5.5V, which mainly supplies power for Main Regulator, IO and clock reset system.

- V_{DD} domain: The voltage regulator supplies power for the CPU, AHB, APB, SRAM, Flash and most digital peripheral interfaces.

PWR is the power control module of the entire device, with main function being to control N32G003 to enter different power modes and be awakened by other events or interrupts. N32G003 supports RUN, STOP and PD modes.

2.7 Programmable Voltage Detector

Power-on reset (POR) and power-down reset (PDR) circuits are always in operation to ensure the system operates when the supply exceeds 2V. When V_{DD} falls below the set threshold (VPOR/PDR), the device is placed in a reset state without using an external reset circuit. There is also a programmable voltage monitor (PVD) in the device that monitors the V_{DD} supply and compares to the threshold VPVD. When V_{DD} is below or above the threshold VPVD, an interrupt will be generated, and the interrupt handler can issue a warning message. The PVD function needs to be enabled through the program. For values of VPOR/PDR and VPVD, refer to [Table 4-6](#).

2.8 Low Power Modes

N32G003 is in RUN mode after system reset or power-on reset. When the CPU does not need to run (e.g. while waiting for an external event), user can choose to enter a low power mode to save power. It depends on the user to choose the optimal low-power mode between low power, short start-up time, and available wakeup sources.

N32G003 has two low power modes:

- STOP mode (most of the clocks are turned off, and the voltage regulator is still running in low power mode)
- PD mode (V_{DD} power down mode, V_{DD} retention, 2 WAKEUP IO and NRST can wake up)
- In addition, the following methods can also reduce the power consumption in RUN mode:
 - Reduce the system clock frequency.
 - Turn off the unused peripheral clocks on the APB and AHB buses.
 - Configure PWR_CTRL4.STBFLH in RUN mode to allow Flash to enter deep standby mode.

2.9 Timers

The N32G003 supports up to 1 advanced timer, 1 general-purpose timer, 1 base timer, as well as 1 watchdog timer and 1 system tick timer.

The following table compares the functions of advanced timer, general-purpose timer and basic timer:

Table 2-1 Comparison of Timer Functions

Timer	Counter Resolution	Counter Type	Prescaler Factor	Capture/ Compare Channels	Complementary Output
TIM1	16bit	Up, down, up/down	Any integer between 1 and 65536	4	Y
TIM3	16bit	Up, down, up/down	Any integer between 1 and 65536	2	N
TIM6	16bit	Up	Any integer between 1 and 65536	0	N

2.9.1 Basic Timer (TIM6)

The basic timer contains a 16-bit counter, as well as provides the ability to wake the system from a low-power mode.

The main functions of the basic timer include:

- 16-bit auto-reload up-counting counter.
- 16-bit programmable prescaler. (The prescaler factor can be configured with any value between 1 and 65536)
- Events that generate the interrupt are as follows:
 - Update event
- Support STOP mode wakeup: When the clock source is configured as LSI, STOP mode can be awakened by updating interrupts (connected to EXTI19).

2.9.2 General-purpose Timer (TIM3)

The general-purpose timers (TIM3) is mainly used in the following occasions: counting the input signal, measuring the pulse width of the input signal and generating the output waveform, etc.

The main functions of the general-purpose timer include:

- 16-bit auto-reload counters. (It can realize up-counting, down-counting, up/down counting)
- 16-bit programmable prescaler. (The prescaler factor can be configured with any value between 1 and 65536)
- Up to 2 channels
- Channel's operating modes: PWM output, output compare, one-pulse mode output, input capture
- The events that generate the interrupt are as follows:
 - Update event
 - Trigger event
 - Input capture
 - Output compare

- Can be controlled by external signal
- Can be linked internally for timer synchronization or chaining
- Supports capturing internal comparator output signals

2.9.3 Advanced-control Timer (TIM1)

The advanced-control timer (TIM1) is mainly used in the following purposes: counting the input signal, measuring the pulse width of the input signals and generating the output waveforms, etc.

Advanced timer has complementary output functions with dead-time insertion and break function. They are suitable for motor control.

The main functions of the advanced timer include:

- 16-bit auto-reload counter. (It can realize up-counting, down-counting, up/down counting)
- 16-bit programmable prescaler. (The prescaler factor can be configured with any value between 1 and 65536)
- Programmable repetition counter
- Up to 5 channels.
- 4 capture/compare channels, the operating modes are PWM output, output compare, one-pulse mode output, input capture.
- The events that generate the interrupt are as follows:
 - Update event
 - Trigger event
 - Input capture
 - Output compare
 - Break input
- Complementary outputs with programmable dead-time
 - For TIM1, channel 1,2,3 support this feature
- Can be controlled by external signal
- Can be linked internally for timer synchronization or chaining
- TIM1_CC5 can be used for COMP blanking

2.9.4 SysTick Timer (Systick)

This timer is dedicated to real-time operating systems and can also be used as a standard down-counting counter.

It has the following characteristics:

- 24 bits down-counter
- Automatic reloading function
- A maskable system interrupt is generated when the counter is 0
- Programmable clock source

2.9.5 Watchdog (WDG)

N32G003 supports one watchdog independent watchdog (IWDG), providing higher security and precise timing.

Independent Watchdog (IWDG)

The independent watchdog is based on a 12-bit down-counter and a 3-bit prescaler. It is driven by a separate low-speed RC oscillator that remains active even if the master clock fails, and can operate in STOP modes. Once activated, if the watchdog is not fed (clears the watchdog counter) within the set time, the IWDG generates a reset when the counter counts to 0x000. It can be used to reset the entire system in the event of an application problem, or as a free timer to provide time-out management for applications. It is hardware or software configurable through the option bytes. Reset and low power wake up are available.

2.10 I²C Bus Interface

The device integrates one independent I²C bus interface, which provide multi-host function to control all I²C bus-specific timing, protocol, arbitration and timeout. Multiple communication rate modes are supported (up to 1MHz). I²C module have a variety of uses, including CRC code generation and verification.

The functions of the I²C interface are described as follows:

- This module can be used as master device or slave device
- I²C master device function:
 - Generate a clock
 - Generate start and stop signals
- I²C slave device function:
 - Programmable address detection
 - The I²C interface supports 7-bit or 10-bit addressing and dual-slave address response capability in 7-bit slave mode

- Stop bit detection
- Generate and detect 7-bit / 10-bit addresses and broadcast calls
- Supports different communication speeds:
 - Standard speed (up to 100 kHz)
 - Fast (up to 400 kHz)
 - Fast + (up to 1MHz)
- Status flags:
 - Transmitter/receiver mode flag
 - Byte transfer complete flag
 - I2C bus busy flag
- Error flags:
 - Arbitration loss in Master mode
 - Acknowledge (ACK) fail after address/data transfer
 - Error start or stop condition detected
 - Overrun or underrun when clock extending is disable
- Interrupt vectors: event interrupt and error interrupt
- Optional extend clock function
- Generation or verification of configurable PEC (Packet error checking):
 - In transmit mode, the PEC value can be transmitted as the last byte
 - PEC error check for the last received byte

2.11 Universal Asynchronous Transceiver (UART)

The N32G003 series intergrate two universal asynchronous transceivers (UART1 and UART2).

UART1 and UART2 interfaces support asynchronous communication mode, multiprocessor communication mode, single-wire half-duplex communication mode.

Main features of USART are as follows:

- Full-duplex asynchronous communication
- Supports NRZ standard format
- Supports single-wire half-duplex communication

- Configurable baud rate
- Supports serial data frame structure with 8 or 9 data bits, 1 or 2 stop bits
- Generation and checking of supported parity bits
- Supports multi-processor communication mode, can enter mute mode, wake up by idle detection or address mark detection
- Supports data overflow error detection, frame error detection, noise error detection, parity error detection
- 8 interrupt requests:
 - Transmit data register empty
 - Transmit complete
 - Receive data register full
 - Idle line detected
 - Data overflow detected
 - Frame error
 - Noise error
 - Parity error

Mode configuration:

UART Modes	UART1	UART2
Asynchronous mode	support	support
Multiprocessor communication	support	support
Half duplex (Single wire mode)	support	support

2.12 Serial Peripheral Interface (SPI)

The device integrates 1 SPI interface. SPI allows the chip to communicate with external devices in half/full-duplex, synchronous, serial manner modes. This interface can be configured in master mode and provide a communication clock (SCK) for external slave devices. The interface can also operate in a multi-master configuration. It can be used for a variety of purposes, including two-wire simplex simultaneous transmission using a single bidirectional data line.

The main functions of SPI interface are as follows:

- Full duplex mode and simplex synchronous mode.
- Supports master mode, slave mode and multi-master mode.
- Supports 8-bit or 16-bit data frame format.
- Data bit sequence programmable.

- NSS management by hardware or software.
- Clock polarity and phase programmable.

2.13 General Purpose Input/Output interface (GPIO)

The device supports 18 GPIOs in 2 groups (GPIOA/GPIOB). GPIOA has 16 pins, while GPIOB has 2 pins. Each GPIO pin can be configured by software as output (push-pull or open drain), input (with or without pull-up or pull-down) or alternate peripheral function ports (output/input). Most GPIO pins are shared with digital or analog alternate peripherals, and some IO pins are also multiplexed with clock pins. Except for ports with analog input function, all GPIO pins have the ability to pass high current.

GPIO ports have the following features:

- GPIO ports can be configured with the following modes by software:
 - Input floating
 - Input pull-up
 - Input pull-down
 - Analog function
 - Open drain output and pull-up/pull-down
 - Push-pull output and pull-up/pull-down
 - Push-pull alternate function and pull-up/pull-down
 - Open-drain alternate function and pull-up/pull-down
- Individual bit setting or bit clearing function
- All I/Os support extended interrupt function
- All I/Os support low power mode wake up, rising or falling edge configurable
 - 18 EXTI lines can be used for wake up in STOP mode, and all I/Os can also be used as EXTI
 - NRST(PA0)/PA1/PA2 three wake up IOs can be used for PD mode wake up, with a maximum I/O filtering time of 1 μ s
- Support software remapping I/O alternate function
- Support GPIO lock mechanism, and reset the lock state to clear

Each I/O port bit can be programmed arbitrarily, but the I/O port register must be accessed as a 32-bit word (16-bit half-word or 8-bit byte are not allowed).

2.14 Analog/Digital Converter (ADC)

The device supports a 12-bit successive approximation ADC with a high-speed analog-to-digital converter. It can measure 10 channel signal sources. It has 9 external sources and 1 internal source. Each channel of the A/D conversion performed in single, continuous or scan mode. ADC measurements are stored (left-aligned/ right-aligned) in 16-bit data registers. The application can detect that the input voltage is within user-defined high/low thresholds by analog watchdog and the maximum frequency of the input clock to the ADC is 24MHz.

The main features of ADC are described as follows:

- Supports 1 ADC, as well as single-ended inputs, and can measure 9 external and 1 internal sources
- Supports 12-bit resolution with a maximum sampling rate of 1MSPS
- ADC clock source is divided into operating clock source and timing clock source
 - HSI as the ADC_CLK operating clock source, up to 24M.
 - HSI as the ADC_1MCLK timing clock source for internal timing functions, and the frequency must be configured to 1MHz.
- Supports timer trigger ADC sampling
- Interrupts when conversion ends, and analog watchdog events occur
- Support 2 conversion modes
 - Single conversion
 - Continuous conversion
- Scan mode supports up to any 5 channels, and each channel has an independent result data register buffer
- All channel sampling intervals can be programmed uniformly
- Regular conversion has external triggering options
- ADC power supply range: 2.4V to 5.5V
- ADC input conversion range: $0 \leq V_{IN} \leq V_{DD}$.

2.15 Analog Comparator (COMP)

One comparator is embedded and can be used as a separate device (all comparator ports are led to I/O), or it can be combined with a timer to form cycle-by-cycle current control in motor control applications with the PWM output from the timer.

The main functions of comparator are as follows:

- Operating voltage range: 2.4~5.5V
- A comparator with subtraction, supports positive port input voltage(500mV~ V_{DD} -200mV) minus a reference

voltage(300/200/100/0mV)

- Support filter clock
- Output polarity can be configured high and low
- The hysteresis configuration can be configured with none, low, medium, or high
- The comparison result can be output to the I/O port or trigger timer, which is used to capture events, OCREF_CLR events, brake events, and generate interrupts
- Input channel can select I/O ports
- Can be equipped with read-only or read-write, and it needs to be reset to unlock when locked
- Support blanking (Blanking), configurable blanking source to generate blanking
- Filter window size can be configured
- Filter threshold size can be configured
- Sampling frequency for filtering can be configured

2.16 Beeper

The beeper module supports complementary outputs and can generate periodic signals to drive external passive buzzers and generate alarm.

2.17 Cyclic Redundancy Check Calculation Unit (CRC)

The device integrated CRC16 functions. The cyclic redundancy check (CRC) calculation unit is based on a fixed generation polynomial to obtain any CRC calculation results. In many applications, CRC-based techniques are used to verify data transfer or storage consistency.

The CRC has the following features:

- CRC16: supports polynomials $X^{16} + X^{15} + X^2 + X^0$
- CRC16 calculation time: 1 AHB clock cycle (HCLK)
- The initial value for cyclic redundancy computing is configurable

2.18 Unique Device Serial Number (UID)

The N32G003 series products have two built-in unique device serial numbers of different lengths, which are 96-bit Unique Device ID (UID) and 128-bit Unique Customer ID (UCID). These two device serial numbers are stored in the system configuration block of Flash memory. The information they contain is written at the time of delivery and is

guaranteed to be unique to any of the N32G003 series microcontrollers under any circumstances and can be read by user applications or external devices through the CPU or SWD interface and cannot be modified.

The 96-bit UID is usually used as a serial number or password. When writing Flash memory, this unique identifier is combined with software encryption and decryption algorithm to further improve the security of code in Flash memory.

UCID is 128-bit, which complies with the definition of national technology chip serial number. It contains the information related to chip production and version.

2.19 Serial Wire SWD Debug Port (SWD)

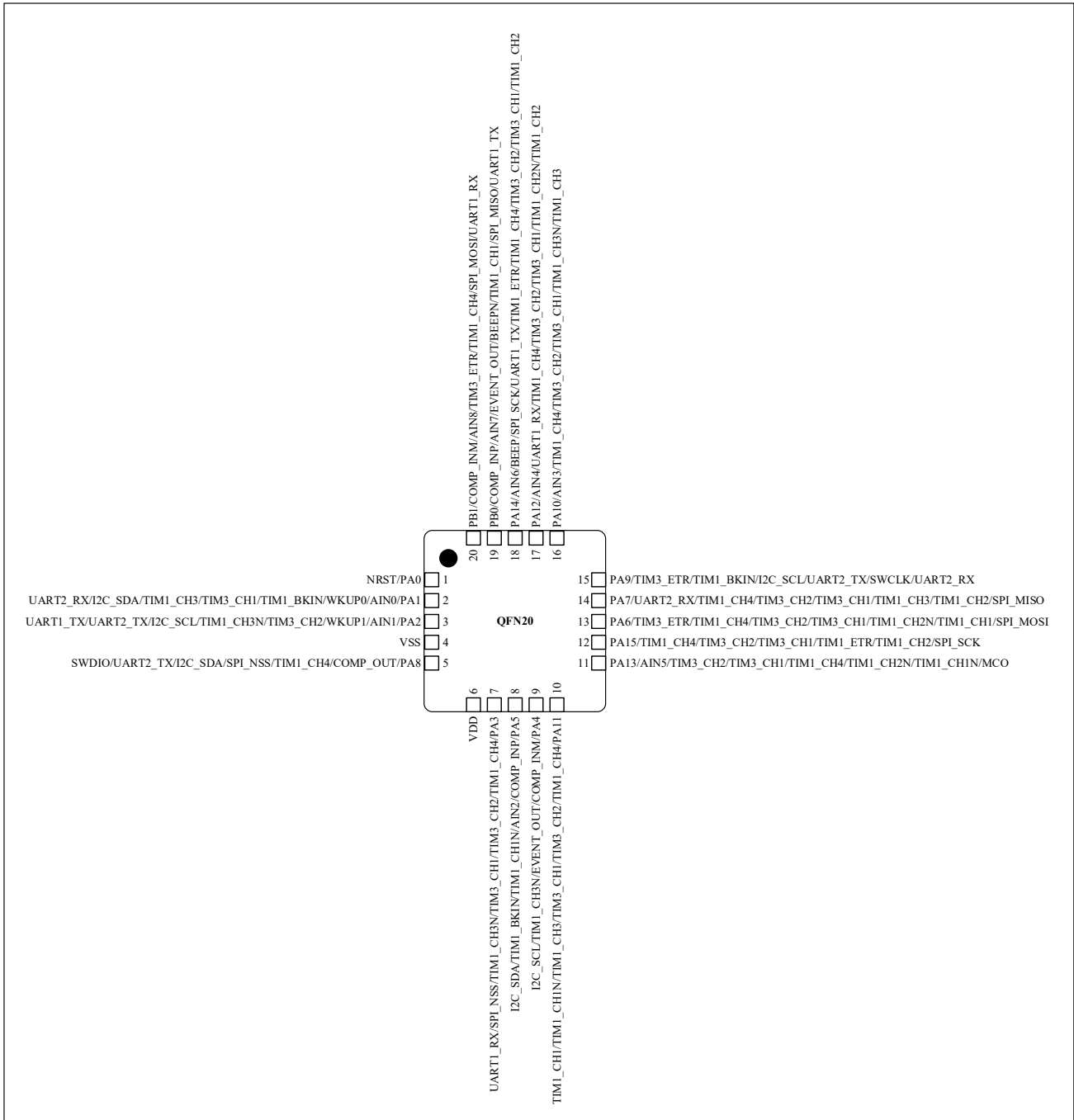
Embedded ARM SWD interface.

3 Pinouts and Pin Description

3.1 Pinouts

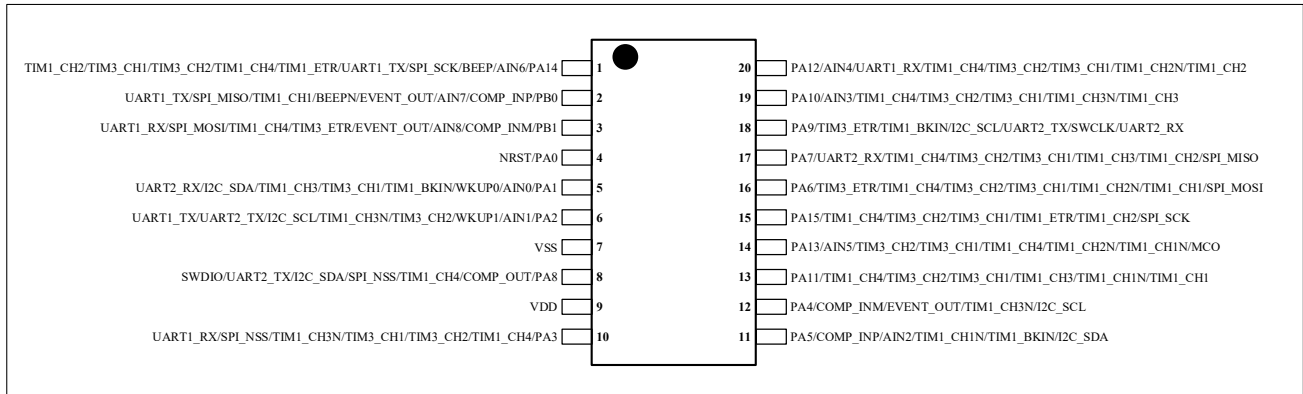
3.1.1 QFN20

Figure 3-1 N32G003 Series QFN20 Pinout



3.1.2 TSSOP20

Figure 3-2 N32G003 Series TSSOP20 Pinout



3.2 Pin Description

Table 3-1 Pin Description

Package		Pin Name(After Reset)	Type ⁽¹⁾	I/O Structure ⁽²⁾	Alternate Functions	
TSSOP20	QFN20				Alternate Functions	Additional Functions
1	18	PA14	I/O	TC	TIM1_CH2 TIM3_CH1 TIM3_CH2 TIM1_CH4 TIM1_ETR UART1_TX SPI_SCK BEEP	AIN6
2	19	PB0	I/O	TC	UART1_TX SPI_MISO TIM1_CH1 BEEP/COMP_IN EVENT_OUT	AIN7 COMP_INP
3	20	PB1	I/O	TC	UART1_RX SPI_MOSI TIM1_CH4 TIM3_ETR EVENT_OUT	AIN8 COMP_INM
4	1	NRST/PA0 ⁽³⁾	I/O	RST/TC	Can be configured as an NRST pin or a normal IO pin	
5	2	PA1	I/O	TC	UART2_RX I2C_SDA TIM1_CH3 TIM3_CH1 TIM1_BKIN WKUP0	AIN0
6	3	PA2	I/O	TC	UART1_TX UART2_TX I2C_SCL TIM1_CH3N TIM3_CH2 WKUP1	AIN1
7	4	VSS	S	-	Power ground	

8	5	PA8 ⁽³⁾ (SWDIO)	I/O	TC	SWDIO UART2_TX I2C_SDA SPI_NSS TIM1_CH4 COMP_OUT	-
9	6	VDD	S	-	Power supply	
10	7	PA3	I/O	TC	UART1_RX SPI_NSS TIM1_CH3N TIM3_CH1 TIM3_CH2 TIM1_CH4	-
11	8	PA5	I/O	TC	I2C_SDA TIM1_BKIN TIM1_CH1N	AIN2 COMP_INP
12	9	PA4	I/O	TC	I2C_SCL TIM1_CH3N EVENT_OUT	COMP_INM
13	10	PA11	I/O	TC	TIM1_CH1 TIM1_CH1N TIM1_CH3 TIM3_CH1 TIM3_CH2 TIM1_CH4	-
14	11	PA13	I/O	TC	MCO TIM1_CH1N TIM1_CH2N TIM1_CH4 TIM3_CH1 TIM3_CH2	AIN5
15	12	PA15	I/O	TC	SPI_SCK TIM1_CH2 TIM1_ETR TIM3_CH1 TIM3_CH2 TIM1_CH4	-
16	13	PA6	I/O	TC	SPI_MOSI TIM1_CH1 TIM1_CH2N TIM3_CH1 TIM3_CH2 TIM1_CH4 TIM3_ETR	-
17	14	PA7	I/O	TC	SPI_MISO TIM1_CH2 TIM1_CH3 TIM3_CH1 TIM3_CH2 TIM1_CH4 UART2_RX	-
18	15	PA9 ⁽³⁾ (SWCLK)	I/O	TC	SWCLK UART2_TX I2C_SCL TIM1_BKIN TIM3_ETR UART2_RX ⁽⁴⁾	-

19	16	PA10	I/O	TC	TIM1_CH3 TIM1_CH3N TIM3_CH1 TIM3_CH2 TIM1_CH4	AIN3
20	17	PA12	I/O	TC	TIM1_CH2 TIM1_CH2N TIM3_CH1 TIM3_CH2 TIM1_CH4 UART1_RX	AIN4

Notes:

⁽¹⁾ I = input, O = output, S = power, Hiz = High-impedance

⁽²⁾ TC: Standard 5V I/O, RST: bidirectional reset pin with built-in weak pull-up resistor

⁽³⁾ During and immediately after the reset, the multiplexing function is not enabled, and the I/O port is configured as an analog input mode (PMODE [1:0] = 2'b11). But there are a few exception signals:

- PA0 is configured as a normal GPIO or NRST pin via an option byte
- After reset, the default state of the pins related to the debugging system is the SWD function, and the SWD pin is configured to input pull-up or pull-down mode:
 - PA9: SWCLK is configured as input pull-down mode
 - PA8: SWDIO is configured as input pull-up mode

⁽⁴⁾ Version A chips do not support PA9 multiplexing to UART2_RX

4 Electrical Characteristics

4.1 Parameter Conditions

All voltages are based on V_{SS} unless otherwise specified.

4.1.1 Minimum and Maximum Values

Unless otherwise specified, all minimums and maximums will be guaranteed under the worst ambient temperature, supply voltage and clock frequency conditions by performing tests on 100% of the product on the production line at ambient temperatures $T_A=25^{\circ}\text{C}$.

Note at the bottom of each form that data obtained through characterization results, design simulation and/or process characteristics will not be tested on the production; Base on characterization, the minimum and maximum values are obtained by taking the average of the samples tested and adding or subtracting three times the standard distribution (mean $\pm 3\sigma$).

4.1.2 Typical Values

Unless otherwise specified, typical data is based on $T_A=25^{\circ}\text{C}$ and $V_{DD}=3.3\text{V}$ ($2\text{V} \leq V_{DD} \leq 5.5\text{V}$ voltage range). These data are only used for design guidance and not tested.

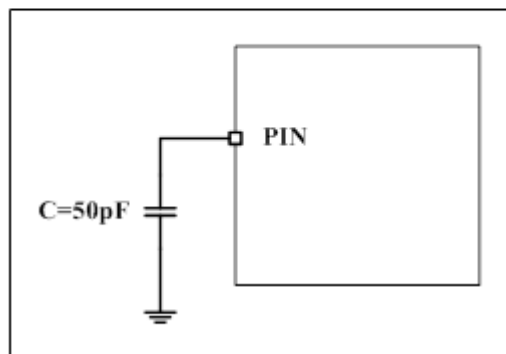
4.1.3 Typical Curves

Unless otherwise specified, typical curves are for design guidance only and have not been tested.

4.1.4 Loading Capacitors

The load conditions when measuring the pin parameters are shown in [Figure 4-1](#).

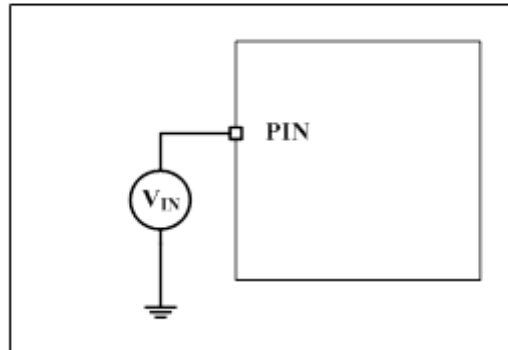
Figure 4-1 Pin Loading Conditions



4.1.5 Pin Input Voltage

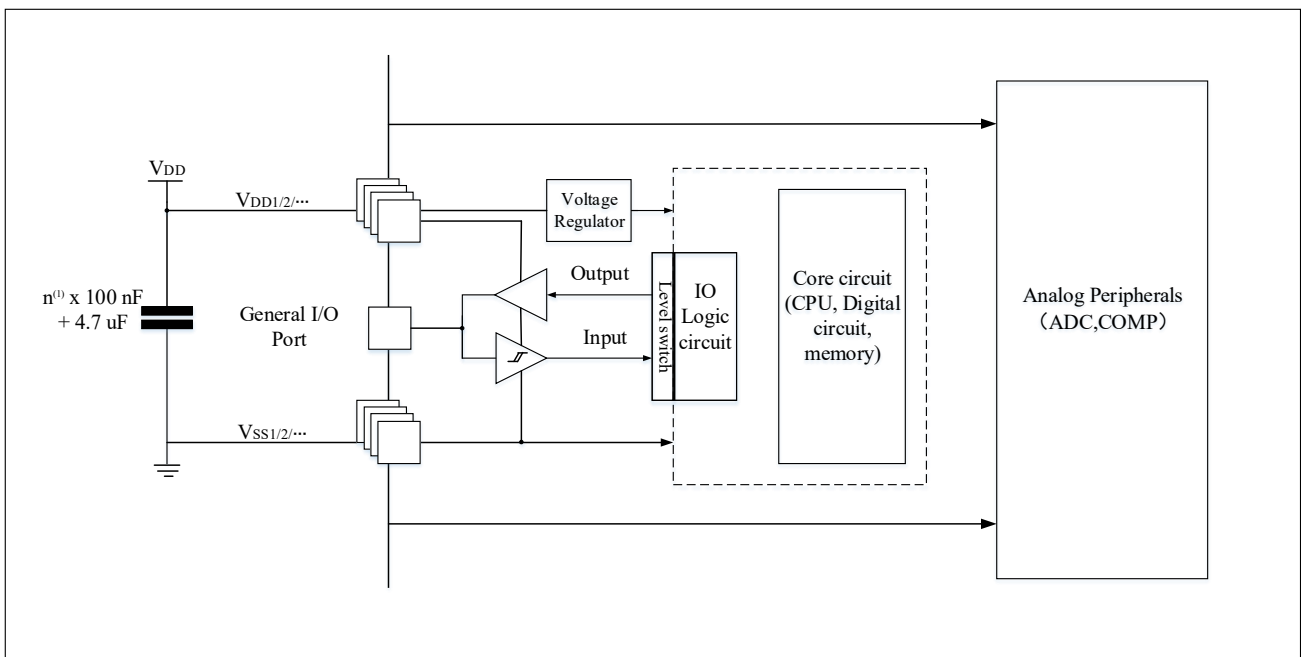
The measurement method of the input voltage on the pin is shown in [Figure 4-2](#).

Figure 4-2 Pin Input Voltage



4.1.6 Power Supply Scheme

Figure 4-3 Power Supply Scheme

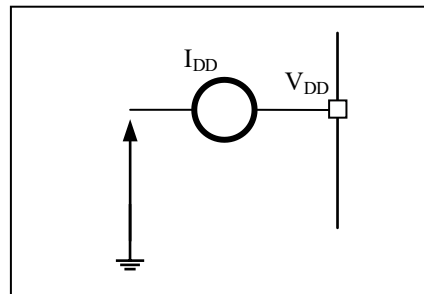


Note: ⁽¹⁾ n is the number of V_{DD}.

Please refer to the hardware design guide for the capacitor connection method.

4.1.7 Current Consumption Measurement

Figure 4-4 Current Consumption Measurement Scheme



4.2 Absolute Maximum Ratings

The load applied to the device may permanently damage the device if it exceeds the values given in the Absolute maximum rating list (Table 4-1, Table 4-2, Table 4-3). The maximum load that can be sustained is only given here, and it does not mean that the functional operation of the device under such conditions is correct. The reliability of the device will be affected when the device works for a long time under the maximum condition.

Table 4-1 Voltage Characteristics

Symbol	Parameter	Min	Max	Unit
$V_{DD} - V_{SS}$	External supply voltage(including V_{DDA} and V_{DD}) ⁽¹⁾	-0.3	5.5	V
V_{IN}	Input voltage on any I/O and control pins	$V_{SS} - 0.3$	$V_{DD} + 0.3$	
$ \Delta V_{DDx} $	Voltage difference between different power supply pins	-	50	mV
$ V_{SSx} - V_{SS} $	Voltage difference between different ground pins	-	50	
$V_{ESD(HBM)}$	ESD electrostatic discharge voltage (human body model)	Refer to Section 4.3.9		

Note: All power (V_{DD} , V_{DDA}) and ground (V_{SS} , V_{SSA}) pins must always be connected to an external power supply within the allowable range.

Table 4-2 Current Characteristics

Symbol	Parameter	Max	Unit
I_{VDD}	Total current into V_{DD}/V_{DDA} power lines ⁽¹⁾	200	mA
I_{VSS}	Total current out of V_{SS} ground lines ⁽¹⁾	200	
I_{IO}	Output current sunk by any I/O and control pin	16	
	Output current source by any I/O and control pins	-16	
$I_{INJ(PIN)}^{(2)}$	Injected current of NRST pin	0/-5	
	Injected current of other pins	+/-5	

Notes:

⁽¹⁾ All power supply (V_{DD}) and ground (V_{SS}) pins must always be connected to the external allowable range of the power supply system.

⁽²⁾ Reverse injection of current can interfere with the analog performance of the device. Refer to [Section 4.3.16](#).

Table 4-3 Temperature Characteristics

Symbol	Parameter	Value	Unit
T _{STG}	Storage temperature range	-40 ~ + 150	°C
T _J	Maximum junction temperature	125	°C

4.3 Operating Conditions

4.3.1 General Operating Conditions

Table 4-4 General Operating Conditions

Symbol	Parameter	Conditions	Min	Max	Unit
f _{HCLK}	Internal AHB clock frequency	-	0	48	MHz
f _{PCLK}	Internal APB clock frequency	-	0	48	
V _{DD}	Standard operating voltage	-	2	5.5	V
	When using an ADC, analog partial operating voltage	-	2.4	5.5	V
	When using an COMP, analog partial operating voltage	-	2.4	5.5	V
T _A	Temperature range	7 suffix version	-40	105	°C
T _J	Junction temperature range	7 suffix version	-40	125	°C

4.3.2 Operating Conditions at Power-on and Power-off

The parameters given in the following table are based on testing under the ambient temperature listed in [Table 4-4](#).

Table 4-5 Operating Conditions at Power-On and Power-Off

Symbol	Parameter	Conditions	Min	Max	Unit
t _{VDD}	V _{DD} rising time rate	From 0 to V _{DD}	20	∞	μs/V
	V _{DD} falling time rate	From V _{DD} to 0	50	∞	μs/V

4.3.3 Reset and Power Control Module Features

The parameter test conditions in the following table are based on [Table 4-4](#).

Table 4-6 Reset and Power Control Module Features

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{PVD}	Rising	PVD[3:0]=0	1.68	1.88	2.08	V
	Falling	PVD[3:0]=0	1.58	1.78	1.98	
	Rising	PVD[3:0]=1	1.88	2.08	2.28	
	Falling	PVD[3:0]=1	1.78	1.98	2.18	
	Rising	PVD[3:0]=2	2.08	2.28	2.48	
	Falling	PVD[3:0]=2	1.98	2.18	2.38	
	Rising	PVD[3:0]=3	2.28	2.48	2.68	
	Falling	PVD[3:0]=3	2.18	2.38	2.58	
	Rising	PVD[3:0]=4	2.48	2.68	2.88	
	Falling	PVD[3:0]=4	2.38	2.58	2.78	
	Rising	PVD[3:0]=5	2.68	2.88	3.08	

	Falling	PVD[3:0]=5	2.58	2.78	2.98	
	Rising	PVD[3:0]=6	2.86	3.08	3.3	
	Falling	PVD[3:0]=6	2.76	2.98	3.2	
	Rising	PVD[3:0]=7	3.06	3.28	3.5	
	Falling	PVD[3:0]=7	2.96	3.18	3.4	
	Rising	PVD[3:0]=8	3.26	3.48	3.7	
	Falling	PVD[3:0]=8	3.16	3.38	3.6	
	Rising	PVD[3:0]=9	3.46	3.68	3.9	
	Falling	PVD[3:0]=9	3.36	3.58	3.8	
	Rising	PVD[3:0]=10	3.66	3.88	4.1	
	Falling	PVD[3:0]=10	3.56	3.78	4	
	Rising	PVD[3:0]=11	3.82	4.08	4.34	
	Falling	PVD[3:0]=11	3.72	3.98	4.24	
	Rising	PVD[3:0]=12	4.02	4.28	4.54	
	Falling	PVD[3:0]=12	3.92	4.18	4.44	
	Rising	PVD[3:0]=13	4.22	4.48	4.74	
	Falling	PVD[3:0]=13	4.12	4.38	4.64	
	Rising	PVD[3:0]=14	4.42	4.68	4.94	
	Falling	PVD[3:0]=14	4.32	4.58	4.84	
	Rising	PVD[3:0]=15	4.62	4.88	5.14	
	Falling	PVD[3:0]=15	4.52	4.78	5.04	
$V_{PVDhyst}^{(1)}$	PVD hysteresis	-	80	100	125	mV
V_{LVR}	Rising	LVR[3:0]=0	1.68	1.88	2.08	V
	Falling	LVR[3:0]=0	1.58	1.78	1.98	
	Rising	LVR[3:0]=1	1.88	2.08	2.28	
	Falling	LVR[3:0]=1	1.78	1.98	2.18	
	Rising	LVR[3:0]=2	2.08	2.28	2.48	
	Falling	LVR[3:0]=2	1.98	2.18	2.38	
	Rising	LVR[3:0]=3	2.28	2.48	2.68	
	Falling	LVR[3:0]=3	2.18	2.38	2.58	
	Rising	LVR[3:0]=4	2.48	2.68	2.88	
	Falling	LVR[3:0]=4	2.38	2.58	2.78	
	Rising	LVR[3:0]=5	2.68	2.88	3.08	
	Falling	LVR[3:0]=5	2.58	2.78	2.98	
	Rising	LVR[3:0]=6	2.86	3.08	3.3	
	Falling	LVR[3:0]=6	2.76	2.98	3.2	
	Rising	LVR[3:0]=7	3.06	3.28	3.5	
	Falling	LVR[3:0]=7	2.96	3.18	3.4	
	Rising	LVR[3:0]=8	3.26	3.48	3.7	
	Falling	LVR[3:0]=8	3.16	3.38	3.6	
	Rising	LVR[3:0]=9	3.46	3.68	3.9	
	Falling	LVR[3:0]=9	3.36	3.58	3.8	
	Rising	LVR[3:0]=10	3.66	3.88	4.1	
	Falling	LVR[3:0]=10	3.56	3.78	4	
	Rising	LVR[3:0]=11	3.82	4.08	4.34	
	Falling	LVR[3:0]=11	3.72	3.98	4.24	
Rising	LVR[3:0]=12	4.02	4.28	4.54		

	Falling	LVR[3:0]=12	3.92	4.18	4.44	
	Rising	LVR[3:0]=13	4.22	4.48	4.74	
	Falling	LVR[3:0]=13	4.12	4.38	4.64	
	Rising	LVR[3:0]=14	4.42	4.68	4.94	
	Falling	LVR[3:0]=14	4.32	4.58	4.84	
	Rising	LVR[3:0]=15	4.62	4.88	5.14	
	Falling	LVR[3:0]=15	4.52	4.78	5.04	
$V_{LVRhyst}^{(1)}$	LVR hysteresis	-	80	100	125	mV
$V_{POR/PDR}$	V_{DD} Power on/down Reset threshold	-	-	1.53	-	V
$T_{RSTEMPO}^{(1)}$	Reset temporization	-	-	150		us

Note: ⁽¹⁾ Guaranteed by design, not tested in production.

4.3.4 Internal Reference Voltage

The parameter test conditions in the following table are based on [Table 4-4](#).

Table 4-7 Internal Reference Voltage

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{REFINT}	Internal reference voltage	$-40^{\circ}\text{C} < T_A < +105^{\circ}\text{C}$	-	1.21	-	V
$T_{S_vrefint}^{(1)}$	When reading the internal reference voltage, the sampling time of the ADC	PLS[3:0]=0001 (Rising edge), $f_{ADC_CLK}=24\text{M}$	-	15.8	-	μs

Note: ⁽¹⁾ The shortest sampling time is obtained through multiple loops in the application.

4.3.5 Power Supply Current Characteristics

Current consumption is a combination of several parameters and factors, including operating voltage, ambient temperature, load of I/O pins, software configuration of the product, operating frequency, I/O pin flip rate, program location in memory, and code executed.

The measurement method of current consumption is illustrated in [Figure 4-4](#).

All of the current consumption measurements given in this section are while executing a reduced set of code.

4.3.5.1 Maximum current consumption

The chip test conditions are as follows:

- All I/O pins are in input mode and connected to a static level— V_{DD} or V_{SS} (no load).
- All peripherals are in the off state, unless otherwise specified.
- The access time of Flash memory is adjusted to the frequency of f_{HCLK} (0~24MHz is 0 waiting period, 24~48MHz is 1 waiting period).

- The command prefetch function is enabled (Note: this parameter must be set before setting the clock and bus prescaler).
- When the peripheral is turned on: $f_{PCLK} = f_{HCLK}$.

The parameter test conditions in the following table are based on [Table 4-4](#).

Table 4-8 Typical Current Consumption in RUN Mode When Running Code from Flash

Symbol	Parameter	Conditions	f_{HCLK}	Typ ⁽¹⁾		Unit
				$T_A = 105^\circ\text{C}$		
I_{DD}	Supply current in RUN mode	External clock ⁽²⁾ , Enable all peripherals	48MHz	4.92		mA
			40MHz	4.03		
			24MHz	3.0		
			8MHz	2.01		
		External clock ⁽²⁾ , Disable all peripherals	48MHz	4.0		
			40MHz	3.3		
			24MHz	2.51		
			8MHz	1.8		

Note: ⁽¹⁾ Guaranteed by characterization, not tested in production.

4.3.5.2 Typical current consumption

The chip test conditions are as follows:

- All I/O pins are in input mode and connected to a static level— V_{DD} or V_{SS} (no load).
- All peripherals are disabled unless otherwise specified.
- The access time of Flash memory is adjusted to the frequency of f_{HCLK} (0~24MHz is 0 waiting period, 24~48MHz is 1 waiting period).
- The command prefetch function is enabled (Note: this parameter must be set before setting the clock and bus prescaler).
- When the peripheral is turned on: $f_{PCLK} = f_{HCLK}$, $f_{ADCCCLK} = f_{PCLK}/2$.

The parameter test conditions in the following table are based on [Table 4-4](#).

Table 4-9 Typical Current Consumption in RUN Mode When Running Code from Flash

Symbol	Parameter	Conditions	f_{HCLK}	Typ ⁽¹⁾		Unit
				Enable All Peripherals ⁽²⁾	Disable All Peripherals	
I_{DD}	Current in RUN mode	Internal high-speed RC oscillator (HSI)	48MHz	4.91	3.99	mA
			40MHz	4.02	3.28	
			24MHz	2.98	2.49	
			8MHz	1.94	1.74	

Note: ⁽¹⁾ The typical value is obtained by testing at $T_A = 25^\circ\text{C}$ $V_{DD} = 3.3\text{V}$.

4.3.5.3 Low power mode current consumption

The microcontroller is under the following conditions:

- All I/O pins are in input mode and are connected to a static level — V_{DD} or V_{SS} (no load).
- All peripherals are disabled unless otherwise noted.

Table 4-10 Typical Current Consumption in STOP and PD Mode

Symbol	Parameter	Condition	Typ ⁽¹⁾	Max ⁽¹⁾	Unit
			$V_{DD} = 3.3\text{ V}$		
I_{DD_STOP}	Current in STOP mode	LSI=32KHz, HCLK off, 3KB SRAM hold, all GPIO status hold, register hold.	2	-	uA
I_{DD_PD}	Current in PD mode	All functional modules are turned off and support 2-way IO wakeup.	0.5	-	uA

Note: ⁽¹⁾ The typical value/maximum value is tested is obtained by testing at $T_A=25\text{ }^\circ\text{C}$.

4.3.6 Internal Clock Source Characteristics

The characteristic parameters given in the following table were measured using ambient temperature and supply voltage in accordance with [Table 4-4](#).

4.3.6.1 High-speed internal (HSI) RC oscillator

Table 4-11 HSI Oscillator Characteristics⁽¹⁾⁽²⁾

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{HSI}	Frequency	HSI=48M , $V_{DD}=3.3\text{V}$, $T_A = 25^\circ\text{C}$, After calibration	47.52 ⁽³⁾	48	48.48 ⁽³⁾	MHz
		HSI=40M , $V_{DD}=3.3\text{V}$, $T_A = 25^\circ\text{C}$, After calibration	39.6 ⁽³⁾	40	40.4 ⁽³⁾	MHz
$DuCy_{(HSI)}$	Duty cycle	-	45	-	55	%
ACC_{HSI}	HSI oscillator frequency drift over temperature ⁽⁴⁾	$V_{DD}=3.3\text{V}$, $T_A = -40\sim 105^\circ\text{C}$	-2	-	2.7	%
		$V_{DD}=3.3\text{V}$, $T_A = -20\sim 85^\circ\text{C}$	-1.5	-	2.7	%
		$V_{DD}=3.3\text{V}$, $T_A = 0\sim 70^\circ\text{C}$	-1	-	2	%
$t_{SU(HSI)}$	HSI startup time	-	2	-	7	μs
$I_{DD(HSI)}$	HSI power consumption	-	-	250	400	μA

Notes:

⁽¹⁾ Unless otherwise specified, $V_{DD} = 3.3\text{V}$, $T_A = -40\sim 105^\circ\text{C}$.

⁽²⁾ Guaranteed by design, not tested in production.

⁽³⁾ Production calibration accuracy, excluding welding effects. Welding brings about 1% prescaler range.

⁽⁴⁾ Prescaler includes the effect of welding, data is from sample testing, not tested in production.

4.3.6.2 Low-speed internal (LSI) RC oscillator

Table 4-12 LSI Oscillator Characteristics⁽¹⁾

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f _{LSI} ⁽²⁾	Frequency	V _{DD} =3.3V, T _A = 25°C, After calibration	31	32	33	KHz
		V _{DD} =2V ~5.5V, T _A = -40~105°C	26	32	38	KHz
t _{SU(LSI)} ⁽²⁾	LSI Startup Time		-	30	80	μs
I _{DD(LSI)} ⁽²⁾	LSI power consumption		-	0.3	-	μA

Notes:

⁽¹⁾ Unless otherwise specified, V_{DD} = 3.3V, T_A = -40~105°C.

⁽²⁾ Guaranteed by design, not tested in production.

4.3.7 Low-power Mode Wakeup Time

The wakeup time listed in [Table 4-20](#) is measured during the wakeup phase of a 48MHz HSI RC oscillator. The clock source used when waking up depends on the current operating mode:

- STOP or PD mode: clock source is RC oscillator

The parameter test conditions in the following table are based on [Table 4-4](#).

Table 4-13 Low-power Mode Wakeup Time

Symbol	Parameter	Typ	Unit
t _{WUSTOP} ⁽¹⁾	Wake up from STOP mode	22	us
t _{WUPD} ⁽¹⁾	Wake up from PD mode	560	us

Note: ⁽¹⁾ The measurement of the wakeup time is from the start of the wakeup event to the user program reading the first instruction.

4.3.8 FLASH Memory Characteristics

Unless otherwise specified, all characteristic parameters are obtained at T_A = -40~105°C.

Table 4-14 Flash Memory Characteristics

Symbol	Parameter	Conditions	Min ⁽¹⁾	Typ ⁽¹⁾	Max ⁽¹⁾	Unit
t _{PROG}	Word programming time(32-bit)	T _A = -40~105°C	-	175	-	μs
t _{ERASE}	Page erase time(512Bytes)	T _A = -40~105°C	-	2.27	-	ms
t _{ME}	Mass erase time	T _A = -40~105°C; BOOT UNLOCK	-	70.6	-	ms
		T _A = -40~105°C; BOOT LOCK	-	132.8	-	ms
I _{DD}	Current ⁽¹⁾	Read, f _{HCLK} =48MHz, V _{DD} =3.3V	-	2	2.4	mA
		Write, f _{HCLK} =48MHz, V _{DD} =3.3V	-	-	1.2	mA
		Erase, f _{HCLK} =48MHz, V _{DD} =3.3V	-	-	0.6	mA
		PD/STOP mode, V _{DD} =3.3~3.6V	-	-	150	μA

Note: ⁽¹⁾ Guaranteed by design, not tested in production.

Table 4-15 Flash Endurance and Data Retention Life

Symbol	Parameter	Conditions	Min ⁽¹⁾	Unit
N _{END}	Endurance(Note: erasing and writing cycle)	T _A = -40~105°C	100	kcycles
t _{RET}	Data retention	T _A = 105°C, after 1000 erasing cycle ⁽¹⁾	10	years

Note: ⁽¹⁾ Guaranteed by characterization, not tested in production.

4.3.9 Electrical Sensitivity

Based on three different tests (ESD, LU), a specific measurement method is used to test the strength of the chip to determine its performance in terms of electrical sensitivity.

Electrostatic discharge (ESD)

Electrostatic discharge (a positive pulse followed by a negative pulse one second later) is applied to all pins of all samples.

Table 4-16 ESD Characteristics

Symbol	Parameter	Conditions	Class	Max ⁽¹⁾	Unit
V _{ESD(HBM)}	Electrostatic discharge voltage (human body model)	T _A = +25 °C, In accordance with MIL-STD-883K Method 3015.9	2	4000	V
V _{ESD(CDM)}	Electrostatic discharge voltage (charged device model)	T _A = +25 °C, In accordance with ESDA/JEDEC JS-002-2018	II	1000	

Note: ⁽¹⁾ Guaranteed by characterization, not tested in production.

Static latch-up(LU)

To evaluate the locking performance, two complementary static latch-up tests were performed on six samples:

- Supply voltage exceeding limit for each power pin.
- Current is injected into each input, output, and configurable I/O pin.

This test conforms to EIA/JESD78E IC latch standard.

Table 4-17 Electrical Sensitivity

Symbol	Parameter	Conditions	Class
LU	Static Latch-up class	T _A = +105 °C, conforming to JESD78E	II level A

4.3.10 I/O Port Characteristics

Generic input/output characteristics

The parameter test conditions in the following table are based on [Table 4-4](#). All I/O ports are CMOS and TTL compatible.

Table 4-18 I/O Static Characteristics

Symbol	Parameter	V _{DD}	Conditions	Min	Max	Unit
V _{IL}	Low level input voltage	5	-	-	0.3×V _{DD}	V
		3.3	-	-	0.8	
		2	-	-	0.2×V _{DD}	
V _{IH}	High level input voltage	5	-	0.7×V _{DD}	-	
		3.3	-	2.0	-	
		2	-	0.8×V _{DD}	-	
V _{hys}	Schmitt trigger voltage hysteresis ⁽¹⁾	5/3.3/2	-	0.1×V _{DD}	-	V
I _{lkg} ⁽²⁾	Input leakage current IIH	5/3.3/2	-	-	1	μA
	Input leakage current IIL	5/3.3/2	-	-1	-	
V _{OH}	Output high level voltage	5	High driving I _{min} =16mA low driving I _{min} =8mA	V _{DD} -0.8	-	V
		3.3	High driving I _{min} =8mA low driving I _{min} =4mA	2.4	-	
		2	High driving I _{min} =4mA low driving I _{min} =2mA	V _{DD} -0.45	-	
V _{OL}	Output low level voltage	5	High driving I _{min} =16mA low driving I _{min} =8mA	-	0.7	
		3.3	High driving I _{min} =8mA low driving I _{min} =4mA	-	0.45	
		2	High driving I _{min} =4mA low driving I _{min} =2mA	-	0.4	
R _{PU}	Weak pull-up equivalent resistor	5/3.3/2	-	20	100	kΩ
R _{PD}	Weak pull-down equivalent resistor	5/3.3/2	-	20	100	kΩ
C _{IO}	I/O pin capacitance	5/3.3/2	-	-	10	pF

Notes:

⁽¹⁾ The hysteresis voltage of the Schmitt trigger switching level is based on comprehensive evaluation, not tested in production.

⁽²⁾ If there is reverse current in adjacent pins, the leakage current may be higher than the maximum value.

Input and output AC characteristics

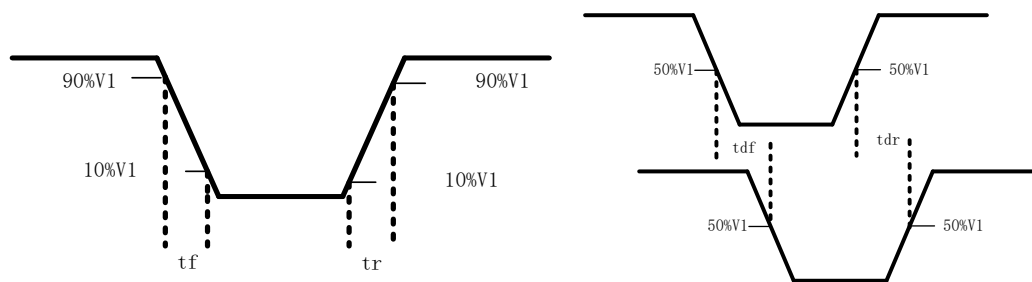
The parameter test conditions in the following table are based on [Table 4-4](#).

Table 4-19 Input/Output AC Characteristics

V _{DD}	Conditions			Rise/Fall Time (ns)			Propagation Delay (ns)		
	Driving	Slew Rate	C _{Loading} (pf)	Min	Typ	Max	Min	Typ	Max
	Strength	Control							
5V(4.5~5.5)	Low (DR=1)	Slow (SR=1)	25	2.56	3.68	6.01	3.96	5.87	9.57
			50	4.76	6.87	11.3	5.01	7.32	11.8
			100	9.24	12.2	21.9	7.46	10.7	17.1
		Fast (SR=0)	25	2.4	3.47	5.71	3.34	5	8.18
			50	4.66	6.72	11.1	4.56	6.69	10.9
			100	9.19	13.3	21.8	7.02	10.1	16.2
	High (DR=0)	Slow (SR=1)	25	1.59	2.28	3.6	3.56	5.33	8.8
			50	2.54	3.65	5.96	4.16	6.17	10.1
			100	4.7	6.83	11.2	5.22	7.64	12.3

		Fast (SR=0)	25	1.32	1.89	3.05	3	4.57	7.58
			50	2.38	3.44	5.65	3.54	5.3	8.7
			100	4.63	6.66	11	4.57	6.72	10.8
3.3V(2.7~3.6)	Low (DR=1)	Slow (SR=1)	25	3.32	5.02	9.31	4.74	7.32	13.6
			50	6.06	9.23	17.4	6.27	9.57	17.7
			100	11.7	17.9	33.6	9.31	14	25.8
		Fast (SR=0)	25	3.06	4.67	8.79	4.17	6.52	12.2
			50	5.91	9.02	17	5.69	8.75	16.2
			100	11.7	17.8	33.5	8.73	13.2	24.3
	High (DR=0)	Slow (SR=1)	25	2.08	3.16	5.84	3.93	6.12	11.4
			50	3.34	5.05	9.27	4.72	7.3	13.6
			100	5.97	9.16	17.2	6.25	9.54	17.6
		Fast (SR=0)	25	1.75	2.66	4.91	3.41	5.41	10.2
			50	3	4.62	8.67	4.16	6.51	12.2
			100	5.87	8.92	16.8	5.66	8.72	16.2
1.8V(1.62~2)	Low (DR=1)	Slow (SR=1)	25	6.08	10.2	18.1	8.41	14.5	26.6
			50	11	18.4	32.9	11	18.9	34.5
			100	21	35	64	16.3	27.6	49.5
		Fast (SR=0)	25	5.58	9.34	16.7	7.38	12.8	23.7
			50	10.6	17.7	32.3	9.98	17.2	31.6
			100	20.8	34.6	63.5	15.2	25.9	43.7
	High (DR=0)	Slow (SR=1)	25	3.77	6.37	11.4	7.05	12.2	22.5
			50	6.11	10.3	18.2	8.42	14.5	26.6
			100	10.9	18.3	32.7	11.4	18.9	34.5
		Fast (SR=0)	25	3.24	5.49	9.8	6.14	10.7	20
			50	5.61	9.4	16.5	7.41	12.9	23.8
			100	10.6	17.6	32	10	17.2	31.6

Figure 4-5 Definition of Input/Output AC Characteristics



4.3.11 NRST Pin Characteristics

The NRST pin is integrated with pull-up resistor. Unless otherwise specified, the parameter test conditions in the following table are based on [Table 4-4](#).

Table 4-20 NRST Pin Characteristics

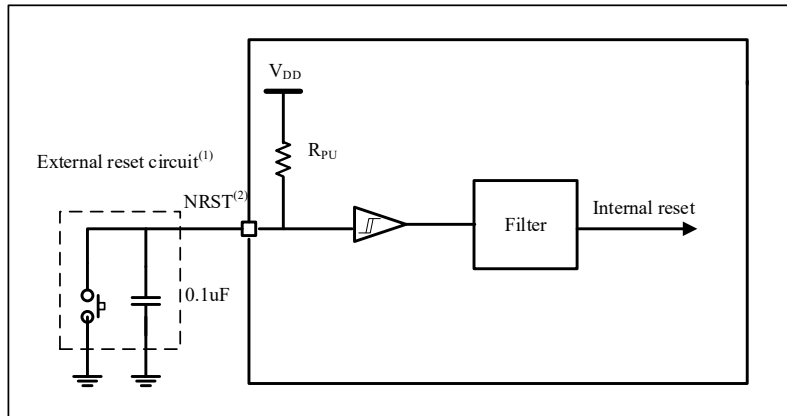
Symbol	Parameter	V _{DD}	Conditions	Min	Typ	Max	Unit
V _{IL(NRST)} ⁽¹⁾	NRST low level input voltage	2V~5.5V	-	-	-	0.3V _{DD}	V
V _{IH(NRST)} ⁽¹⁾	NRST high level input voltage	2V~5.5V	-	0.75V _{DD}	-	-	
V _{hys(NRST)}	NRST schmitt trigger voltage hysteresis	2V~5.5V	-	115	220	315	mV
V _{OL(NRST)} ⁽¹⁾	NRST output low level voltage	5V	High driving I _{min} =16mA low driving I _{min} =8mA	-	-	0.7	V
		3.3V	High driving I _{min} =8mA low driving I _{min} =4mA	-	-	0.45	
		2V	High driving I _{min} =4mA low driving I _{min} =2mA	-	-	0.4	
V _{OH(NRST)} ⁽¹⁾	NRST output high level voltage	5V	High driving I _{min} =16mA low driving I _{min} =8mA	V _{DD} -0.8	-	-	
		3.3V	High driving I _{min} =8mA low driving I _{min} =4mA	2.4	-	-	
		2V	High driving I _{min} =4mA low driving I _{min} =2mA	V _{DD} -0.45	-	-	
R _{PU}	Weak pull-up equivalent resistor ⁽²⁾	2V~5.5V	-	30	60	70	kΩ
V _{F(NRST)} ⁽¹⁾	NRST input filtered pulse	2V	-	-	-	100	ns
		3V~3.6V	-	-	-	100	
		4.5V~5.5V	-	-	-	50	
V _{NF(NRST)} ⁽¹⁾	NRST input unfiltered pulse	2V	-	650	-	-	ns
		3V~3.6V	-	300	-	-	
		4.5V~5.5V	-	200	-	-	

Notes:

⁽¹⁾ Guaranteed by design, note tested in production

⁽²⁾ The pull-up resistor is designed as true resistor for a not switchable PMOS implementation. The resistance of this PMOS switch is very small (about 10%).

Figure 4-6 NRST Pin Protection Recommended Circuit Design



Notes:

(1) The reset network is to prevent parasitic reset.

(2) The user must ensure that the potential of the NRST pin can be lower than the maximum $V_{IL(NRST)}$, otherwise the MCU cannot be reset.

4.3.12 Timer Characteristics

The parameters listed are guaranteed by design.

Table 4-21 TIMx⁽¹⁾ Characteristics

Symbol	Parameter	Conditions	Min	Max	Unit
$t_{res(TIM)}$	Timer step size	-	1	-	$t_{TIMxCLK}$
		$f_{TIMxCLK} = 48MHz$	20.8	-	ns
$f_{EXT}^{(2)}$	Timer external clock frequency on CH1 to CH4	-	0	$f_{TIMxCLK}/2$	MHz
		$f_{TIMxCLK} = 48MHz$	0	24	MHz
Restim	Timer resolution	-	-	16	Bits
$t_{COUNTER}$	Select the internal clock, 16-bit counter clock cycle	-	1	65536	$t_{TIMxCLK}$
		$f_{TIMxCLK} = 48MHz$	0.0208	1365	μs
t_{MAX_COUNT}	Maximum count	-	-	65536×65536	$t_{TIMxCLK}$
		$f_{TIMxCLK} = 48MHz$	-	89.478	s

Notes:

(1) x can be 1, 3, 6.

(2) TIM1 is CH1~CH4, TIM3 is CH1~CH2, TIM6 is not applicable.

4.3.13 IWDG Characteristics

Table 4-22 IWDG Counting Maximum and Minimum Reset Time (LSI = 32KHz)

Prescaler	IWDG_PREDIV.PD[2:0]	Min ⁽¹⁾ IWDG_RELV.REL[11:0]=0	Max ⁽¹⁾ IWDG_RELV.REL[11:0]=0xFFF	Unit
/4	000	0.125	512	ms

/8	001	0.25	1024
/16	010	0.5	2048
/32	011	1	4096
/64	100	2	8192
/128	101	4	16384
/256	11x	8	32768

Note: ⁽¹⁾ Guaranteed by design, not tested in production.

4.3.14 I²C Characteristics

Unless otherwise specified, the parameters use ambient temperature, f_{PCLK} frequency, and V_{DD} supply voltage in accordance with [Table 4-4](#).

The I²C interface of the N32G003 product conforms to the standard I²C communication protocol, but has the following limitations: SDA and SCL are not "true" open leak pins, and when configured for open leak output, the PMOS tube between the pin and V_{DD} is closed, but still exists.

I²C interface features are shown in the following table. Refer to [Section 4.3.10](#) for details about the features of the input/output alternate function pins (SDA and SCL).

Table 4-23 I²C Interface Characteristics

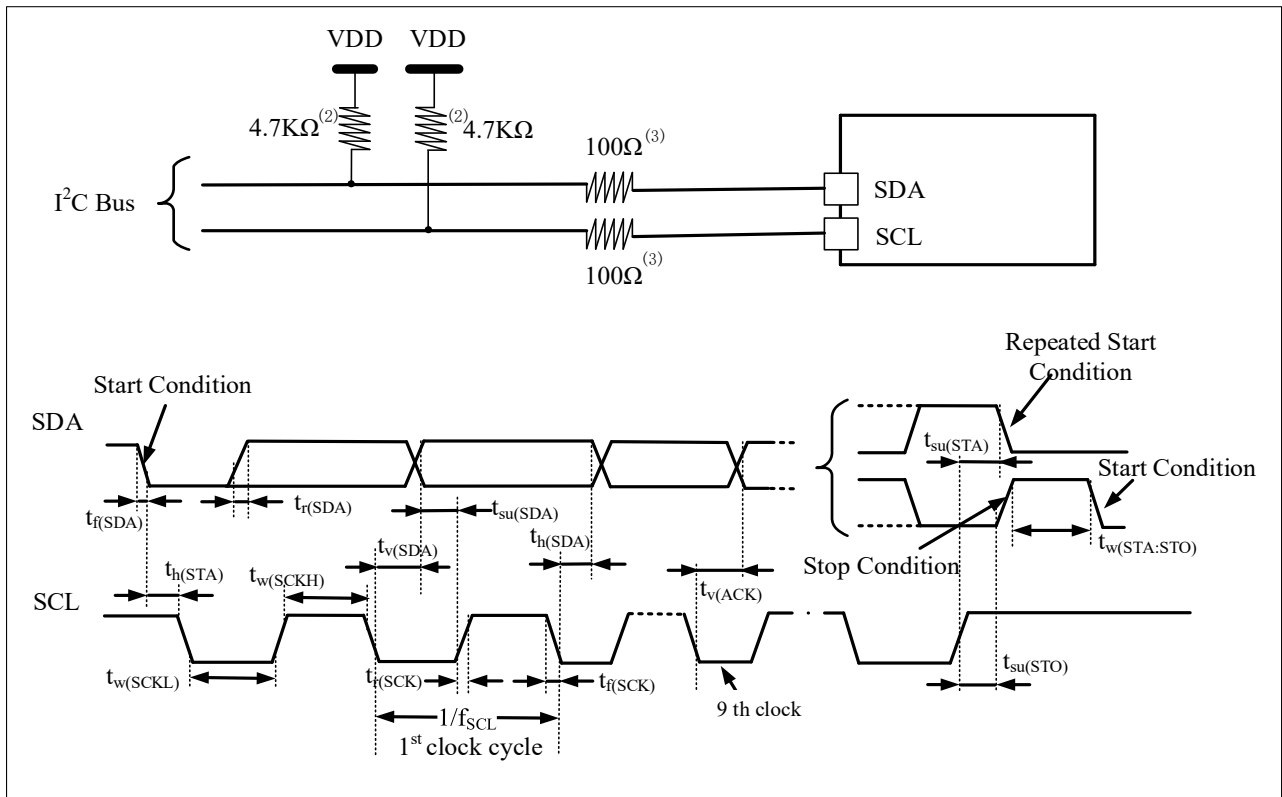
Symbol	Parameter	Standard model		Fast mode		Fast+ mode		Unit
		Min	Max	Min	Max	Min	Max	
f_{SCL}	I ² C interface frequency	0	100	0	400	0	1000	KHz
$t_{h(STA)}$	Start condition holding time ⁽¹⁾	4.0	-	0.6	-	0.26	-	μs
$t_{w(SCLL)}$	SCL clock low time ⁽¹⁾	4.7	-	1.3	-	0.5	-	μs
$t_{w(SCLH)}$	SCL clock high time ⁽¹⁾	4.0	-	0.6	-	0.26	-	μs
$t_{su(STA)}$	Setup time of repeated starting conditions ⁽¹⁾	4.7	-	0.6	-	0.26	-	μs
$t_{h(SDA)}$	SDA data hold time ⁽¹⁾	-	3.4	-	0.9	-	0.4	μs
$t_{su(SDA)}$	SDA setup time ⁽¹⁾	250	-	100	-	50	-	ns
$t_{r(SDA)}$ $t_{r(SCL)}$	SDA and SCL rising time ⁽¹⁾	-	1000	20+0.1Cb	300	-	120	ns
$t_{f(SDA)}$ $t_{f(SCL)}$	SDA and SCL falling time ⁽¹⁾	-	300	20+0.1Cb	300	-	120	ns
$t_{su(STO)}$	Stop condition setup time ⁽¹⁾	4.0	-	0.6	-	0.26	-	μs
$t_{w(STO:STA)}$	Time from stop condition to start condition (bus idle) ⁽¹⁾	4.7	-	1.3	-	0.5	-	μs
C_b	Capacity load per bus ⁽¹⁾	-	400	-	400	-	200	pf
t_{SP}	Spike width suppressed by analog filters in standard and fast modes	0	35	0	35	0	35	ns
$t_v(SDA)$	Data validity time ⁽¹⁾	3.45	-	0.9	-	0.45	-	μs
$t_v(ACK)$	Response validity time ⁽¹⁾	3.45	-	0.9	-	0.45	-	μs

Notes:

⁽¹⁾ Guaranteed by design, not tested in production.

(2) To achieve the maximum frequency of standard mode I2C, f_{CLK} must be greater than 2MHz. To achieve the maximum frequency of fast mode I2C, f_{CLK} must be greater than 4MHz.

Figure 4-7 I²C Bus AC Waveform And Measurement Circuit⁽¹⁾



Notes:

(1) The measuring point is set at $0.3V_{DD}$ and $0.7V_{DD}$.

(2) The pull-up resistance depends on the I2C interface speed.

(3) The resistance value depends on the actual electrical characteristics. The signal line can be directly connected without serial resistance.

4.3.15 SPI Characteristics

Unless otherwise specified, the parameters use ambient temperature, f_{CLK} frequency, and V_{DD} supply voltage in accordance with [Table 4-4](#).

Refer [Section 4.3.10](#) for details on the characteristics of the I/O reuse multiplexed pins (NSS, SCLK, MOSI, MISO).

Table 4-24 SPI Characteristics

Symbol	Parameter	Conditions	Min	Max	Unit
f_{SCLK} $1/t_c(SCLK)$	SPI clock frequency	Master mode	-	12	MHz
		Slave mode	-	12	
$t_r(SCLK)t_f(SCLK)$	SPI clock rising and falling time	Load capacitance: C = 30pF	-	15	ns
DuCy(SCLK)	SPI slave input	SPI Slave mode	30	70	%

	clock duty cycle				
$t_{su(NSS)}^{(1)}$	NSS setup time	Slave mode	$4t_{PCLK}$	-	ns
$t_{h(NSS)}^{(1)}$	NSS hold time	Slave mode	$2t_{PCLK}$	-	ns
$t_{w(SCLKH)}^{(1)}$ $t_{w(SCLKL)}^{(1)}$	SCLK high and low time	Master mode	t_{PCLK}	$t_{PCLK} + 2$	ns
$t_{su(MI)}^{(1)}$	Data entry setup time	Master mode	5	-	ns
$t_{su(SI)}^{(1)}$		Slave mode	5	-	
$t_{h(MI)}^{(1)}$	Data entry hold time	Master mode	5	-	ns
$t_{h(SI)}^{(1)}$		Slave mode	4	-	
$t_{a(SO)}^{(1)(2)}$	Data output access time	Slave mode	0	$3t_{PCLK}$	ns
$t_{dis(SO)}^{(1)(3)}$	Disabled time for data output	Slave mode	2	10	ns
$t_{v(SO)}^{(1)}$	Valid time of data output	Slave mode (after the enabled edge)	-	5	ns
$t_{v(MO)}^{(1)}$		Master mode (after the enabled edge)	-	5	
$t_{h(SO)}^{(1)}$	Data output hold time	Slave mode (after the enabled edge)	15	-	ns
$t_{h(MO)}^{(1)}$		Master mode (after the enabled edge)	2	-	

Notes:

(1) Guaranteed by design, not tested in production.

(2) The minimum value represents the minimum time to drive the output, and the maximum value represents the maximum time to get the data correctly.

(3) The minimum value represents the minimum time to turn off the output, and the maximum value represents the maximum time for placing the data wire in a high resistance state.

Figure 4-8 SPI Sequence Diagram - Slave Mode And CLKPHA=0

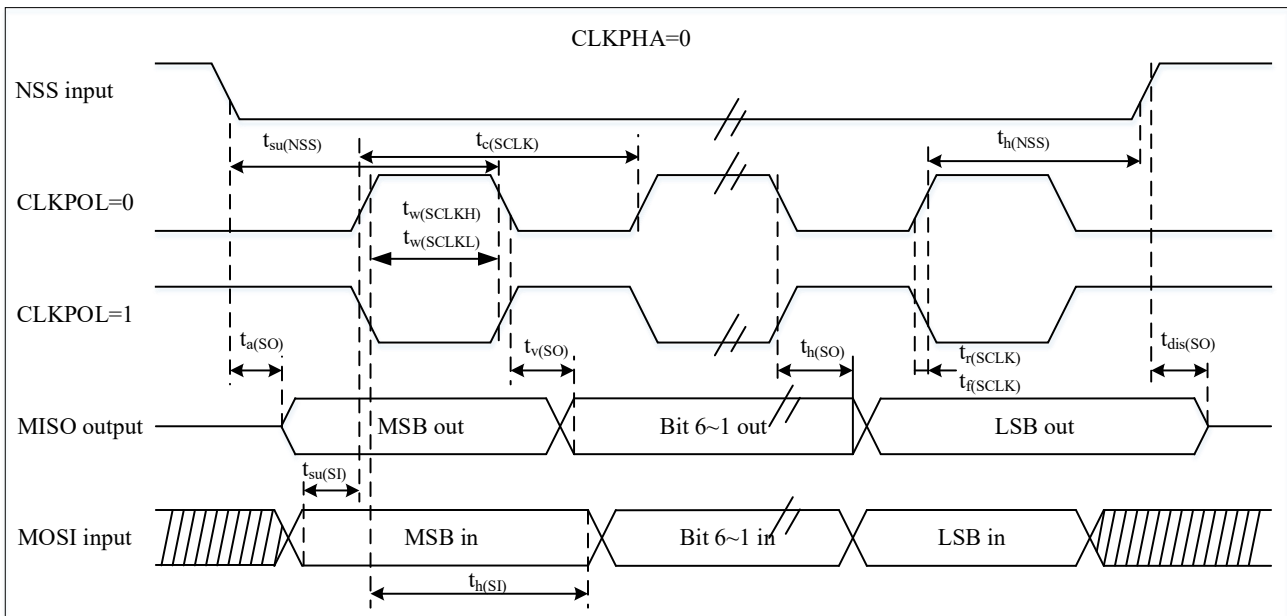
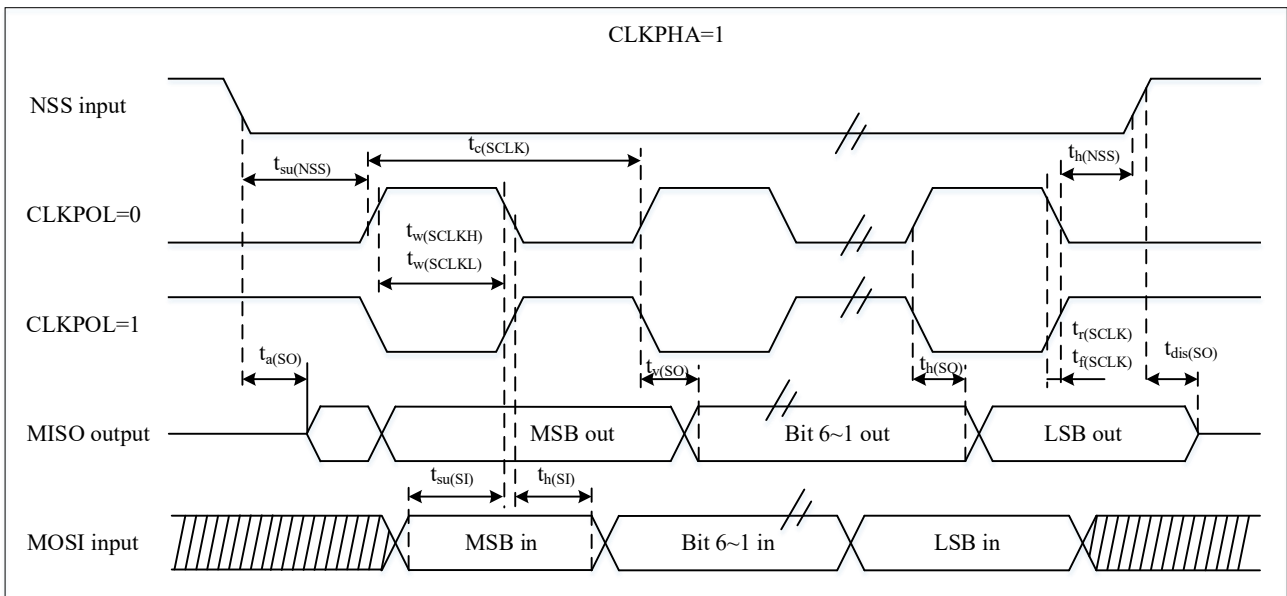
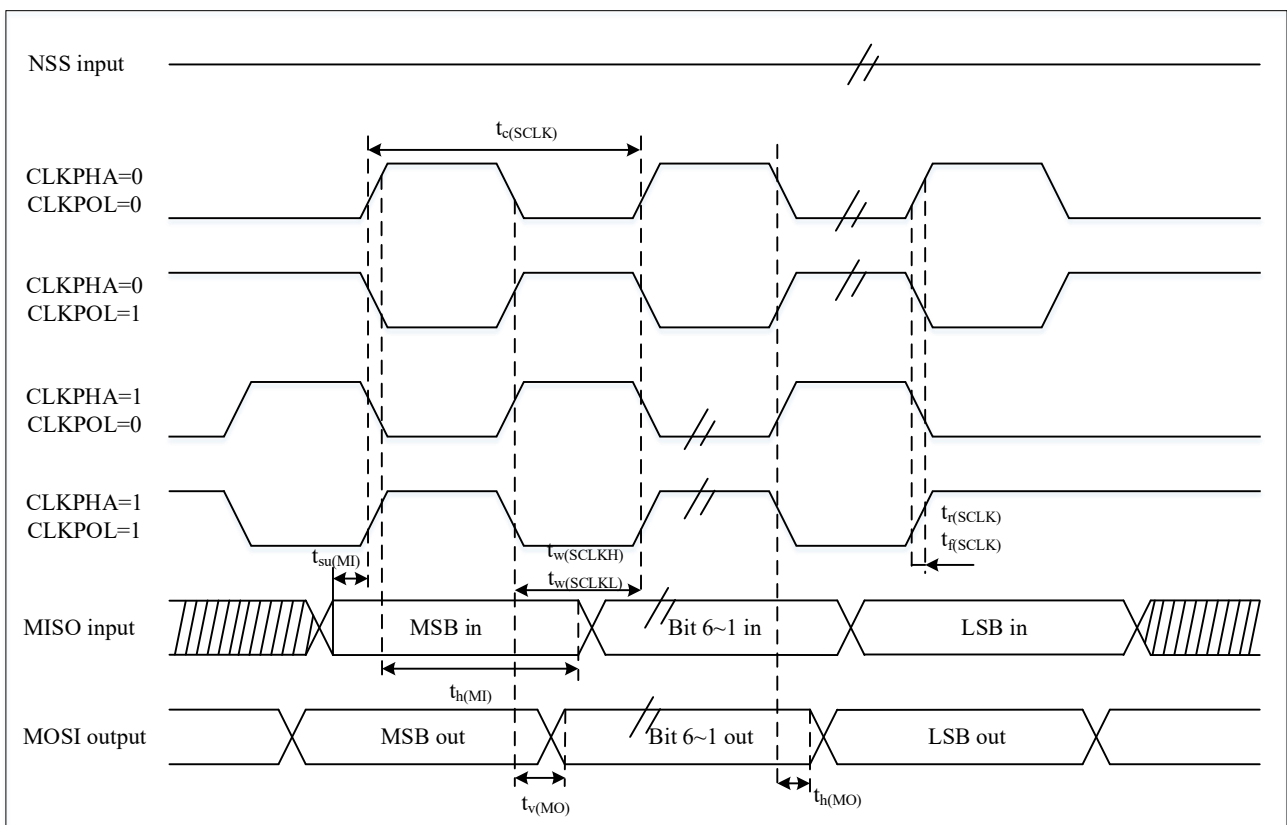


Figure 4-9 SPI Sequence Diagram - Slave Mode And CLKPHA=1⁽¹⁾



Note: ⁽¹⁾ The measurement points were set at the CMOS level of 0.3 V_{DD} and 0.7 V_{DD}.

Figure 4-10 SPI Timing Diagram-Master Mode⁽¹⁾



Note: ⁽¹⁾ The measurement points are set at CMOS level: 0.3 V_{DD} and 0.7 V_{DD}.

4.3.16 ADC Electrical Parameters

Unless otherwise specified, following table parameters are measured using ambient temperature, f_{HCLK} frequency, and V_{DD} supply voltage in accordance with the conditions in [Table 4-4](#).

Note: It is recommended to perform a calibration at each power-on.

Table 4-25 ADC Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DD}^{(1)}$	Supply voltage	-	2.4	3.3	5.5	V
V_{REF+}	Positive reference voltage	-	V_{DD}			V
f_{ADC}	ADC clock frequency	-	-	-	24	MHz
$f_s^{(1)}$	Sampling rate	-	0.03	-	1	Msp/s
V_{AIN}	Conversion voltage range	-	0	-	V_{REF+}	V
$R_{AIN}^{(1)}$	External input impedance	-	Refer to formula 1			Ω
$R_{ADC}^{(1)}$	Internal input resistance	$V_{DD}=3.0V$	-	1500	-	Ω
$C_{ADC}^{(1)}$	Internal sample and hold capacitor	-	-	26	-	pF
SNDR	Signal-to-noise distortion ratio	$V_{DD}=3.3V$	-	58.5	-	dB
$T_s^{(1)}$	Sampling cycle	-	8	-	-	$1/f_{ADC}$
$t_{STAB}^{(1)}$	Power-on time	-	32	-	-	$1/f_{ADC}$
$t_{CONV}^{(1)}$	Conversion time	-	12			$1/f_{ADC}$
I_{ADC}	ADC current consumption	-	-	1.67	-	mA

Note: ⁽¹⁾ Guaranteed by design, not tested in production.

Formula 1: Maximum R_{AIN} formula

$$R_{AIN} < \frac{T_s}{f_{ADC} \times C_{ADC} \times \ln(2^{N+2})} - R_{ADC}$$

The above formula (Formula 1) is used to determine the maximum external impedance so that the error can be less than 1/4 LSB. Where $N=12$ (representing 12-bit resolution).

Table 4-26 ADC Sampling Time⁽¹⁾

Resolution	R_{in} (k Ω)	Minimum Sampling Time (ns)
12-bit	1	500
	1.2	583
	2	833
	3.6	1250
	8.26	2333
	10	3000
	18	5000
	26.9	7583
	35.9	10000
61.9	15833	

Note: ⁽¹⁾ Guaranteed by design, not tested in production.

Table 4-27 ADC Accuracy - Limited Test Conditions⁽¹⁾

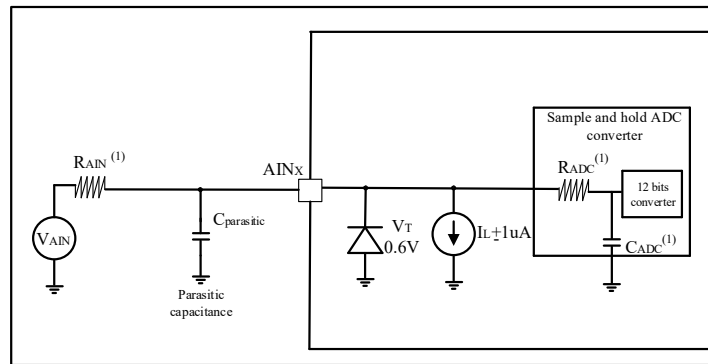
Symbol	Parameter	Conditions	Typ	Max ⁽²⁾	Unit
EG	Gain error	$V_{REF+} = 3.3V$, $T_A = 25\text{ }^\circ\text{C}$, sample rate = 1MSPS, $V_{in} = 0.05V_{DDA} \sim 0.95V_{DDA}$	± 2	± 5	LSB
EO	Offset error		± 0.5	± 2.0	
ED	Differential linearity error		± 0.6	1.5	
EL	Integral linearity error		± 1.5	2.5	
ENOB	Effective number of bits			9.4	-

Notes:

⁽¹⁾ The relationship between the negative injection current and ADC accuracy: the need to avoid negative current is injected on any standard analog input pin, as this significantly reduces the accuracy of the conversion being performed on another analog input. It is recommended to add a Schottky diode (between the pin and ground) on the standard analog pin that may produce negative injection current.

⁽²⁾ Guaranteed by characterization, not tested in production.

Figure 4-11 ADC Typical Connection Diagram



Notes:

⁽¹⁾ For values of R_{AIN} , R_{ADC} , and C_{ADC} , refer to [Table 4-25](#).

⁽²⁾ $C_{parasitic}$ indicates parasitic capacitance on PCB (related to welding and PCB layout quality) and pads (approximately 7pF). A larger $C_{parasitic}$ value would reduce the accuracy of the conversion and the solution was to reduce f_{ADC} .

Comparator (COMP) electrical parameters unless otherwise specified, following table parameters are measured using ambient temperature, f_{HCLK} frequency, and V_{DD} supply voltage in accordance with the conditions in [Table 4-4](#).

Table 4-28 COMP Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DD}	Analog Supply voltage	Normal mode	2.4	-	5.5	V
		With subtractor mode	2.4	-	5.5	
V_{IN}	Input voltage range	V_{IN}	0	-	V_{DD}	mV
		$V_{IN} - 100mV/200mV/300mV$	500	-	$V_{DD}-200$	
$t_{START}^{(1)}$	Comparator startup setup time	Normal mode	-	-	5	us
		With subtractor mode	-	-	15	
t_d		Falling edge	-	304	-	ns

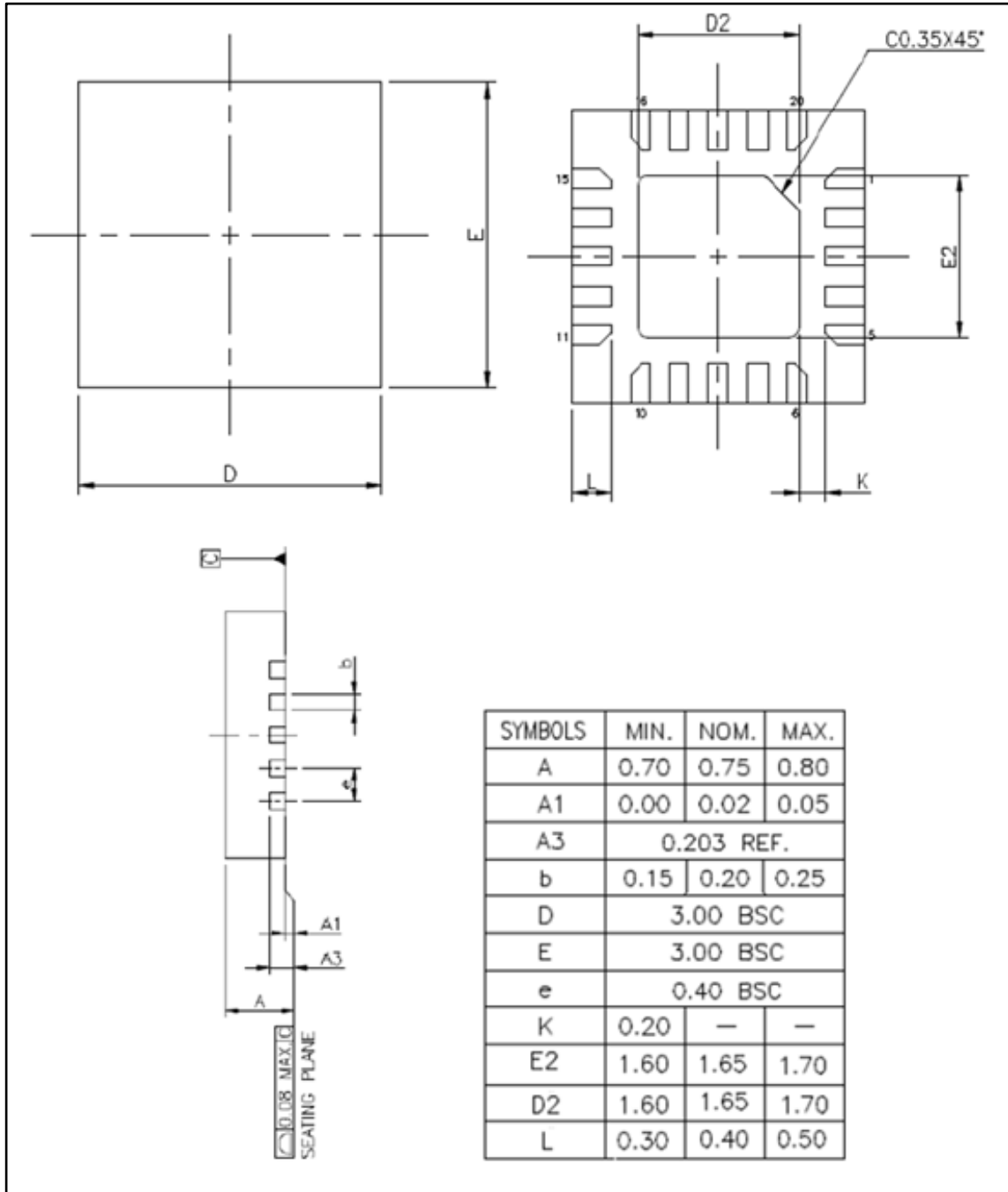
	Propagation delay for 200mV step with 100mV overdrive	Rising edge	-	268	-		
V_{OFFSET}	Comparator input offset error	VIN	-	± 4	± 15	mV	
		VIN - 100mV	-	± 20	± 50		
		VIN - 200mV	-	± 20	± 50		
		VIN - 300mV	-	± 20	± 50		
V_{HYS}	Comparator hysteresis	No hysteresis	-	0	-	mV	
		Low hysteresis	-	10	-		
		Medium hysteresis	-	20	-		
		High hysteresis	-	30	40		
I_{DD}	Comparator current consumption	Normal mode	Static	-	-	50	μA
			With 50kHz ± 100 mV overdrive square signal	-	-	50	
		With subtractor mode	Static	-	-	500	
			With 50 kHz ± 100 mV overdrive square signal	-	-	500	

Note: ⁽¹⁾ Guaranteed by design, not tested in production.

5 Packages

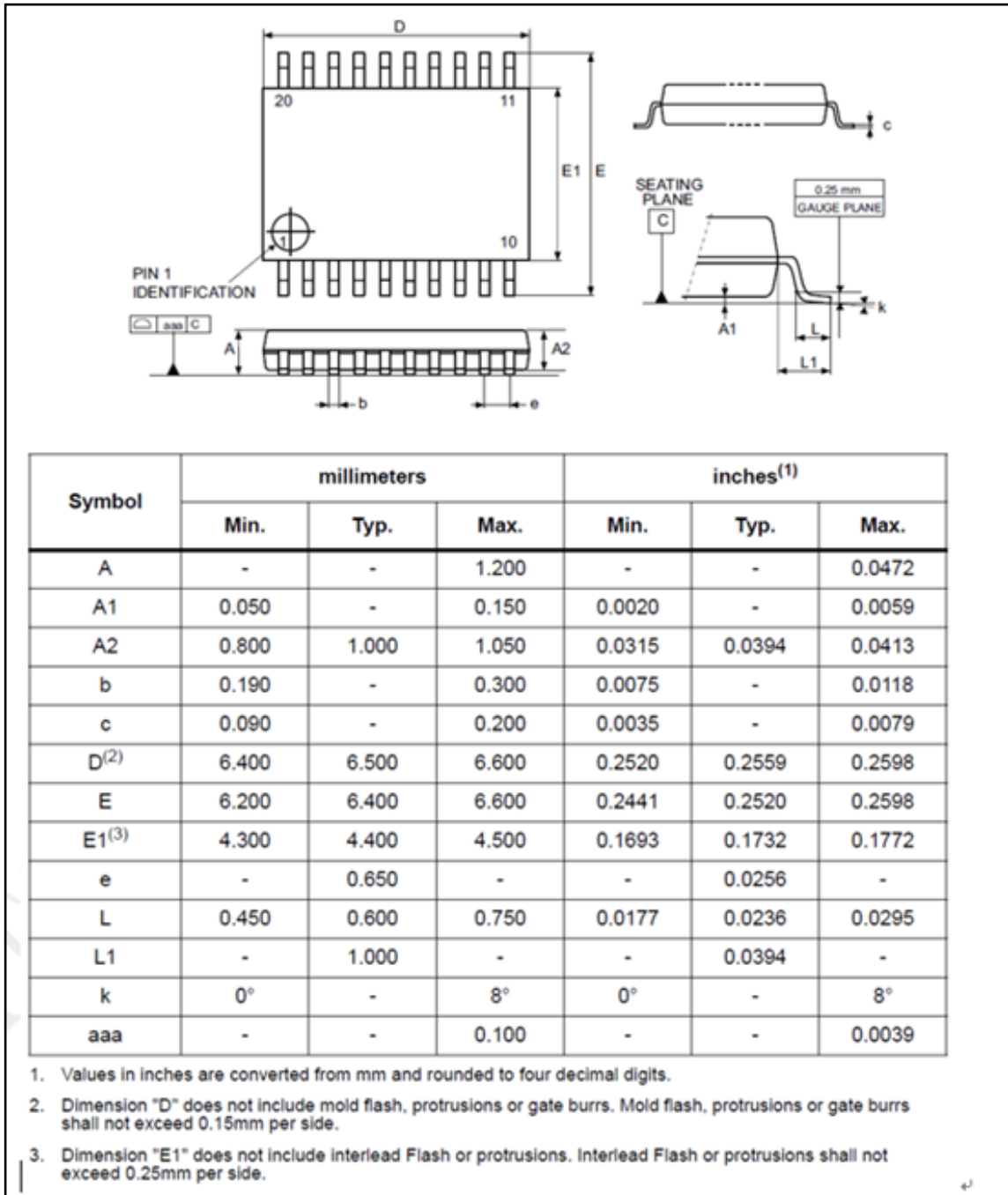
5.1 QFN20(3mm x 3mm)

Figure 5-1 QFN20(3mm x 3mm) Package Dimensions



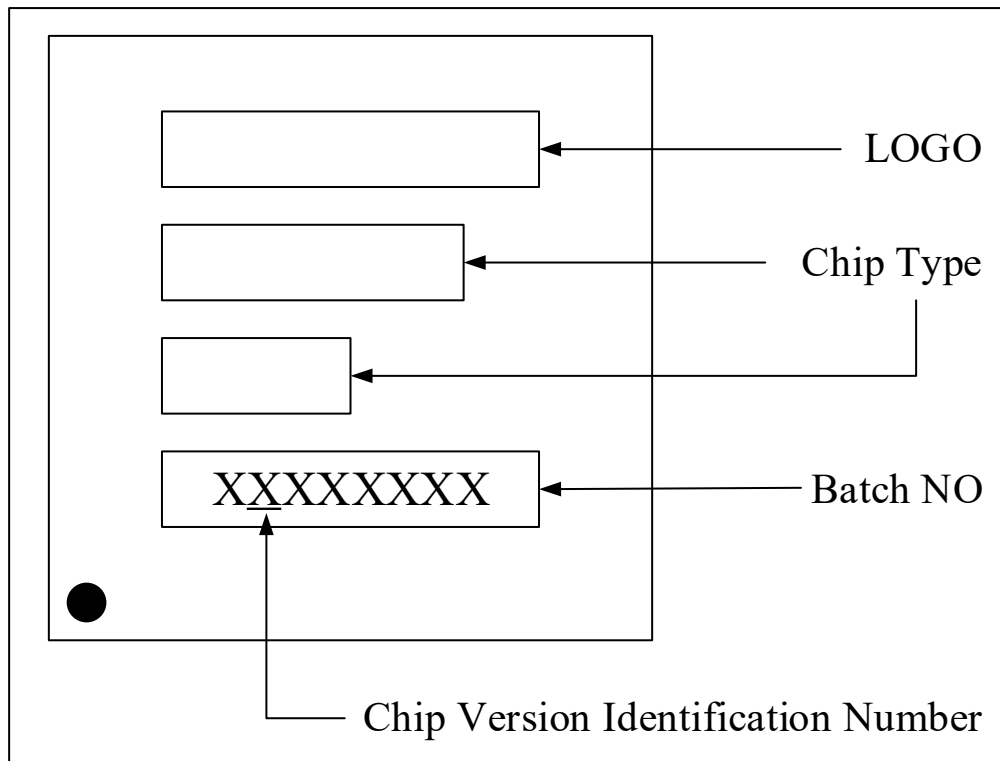
5.2 TSSOP20(6.5mm x 4.4mm)

Figure 5-2 TSSOP20(6.5mm x 4.4mm) Package Dimensions



5.3 Marking Information

Figure 5-3 Marking Information



6 Version History

Version	Date	Changes
V1.0.0	2022.10.26	Initial release
V1.1.0	2023.7.14	1) PA9 added UART2_RX multiplexing function 2) Added N32G003F4S7\N32G003F4Q7 model chips 3) Modified Table 4-6,Table 4-28 data

7 Disclaimer

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